

FIG. 1

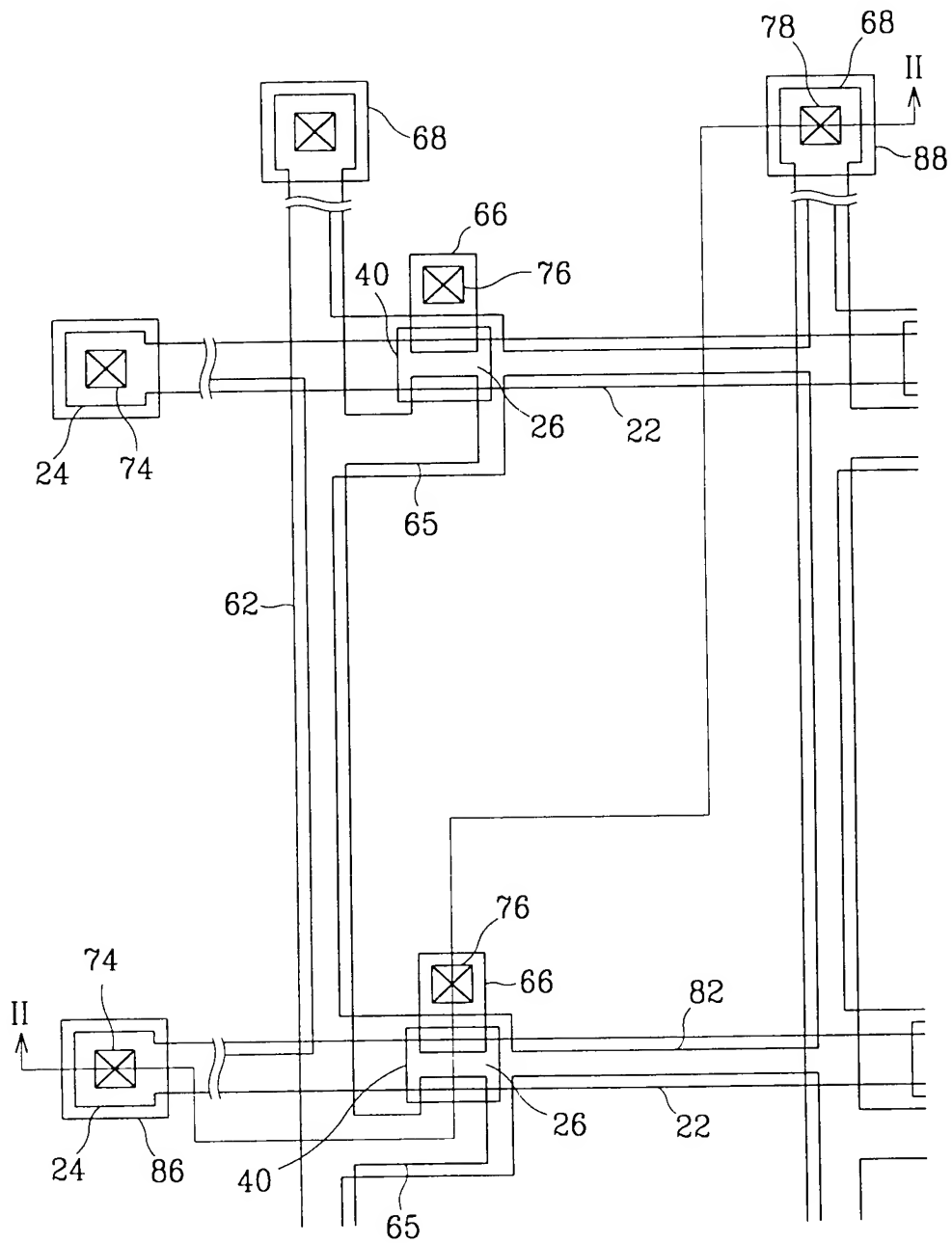


FIG. 2

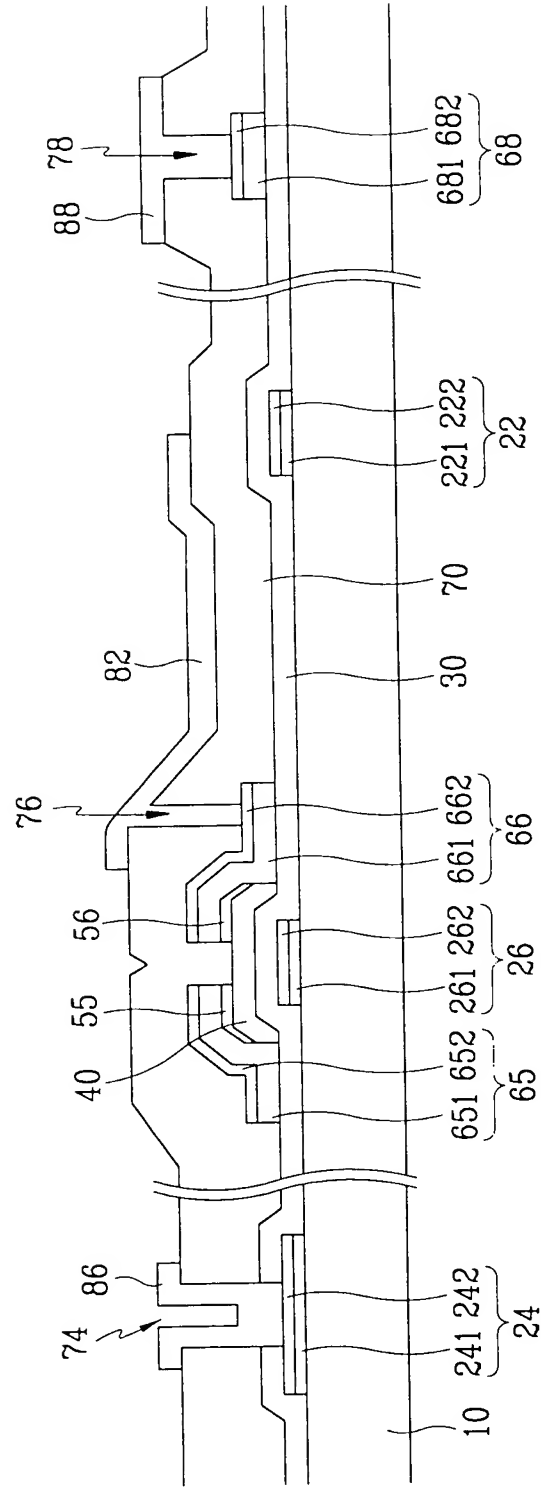


FIG.3A

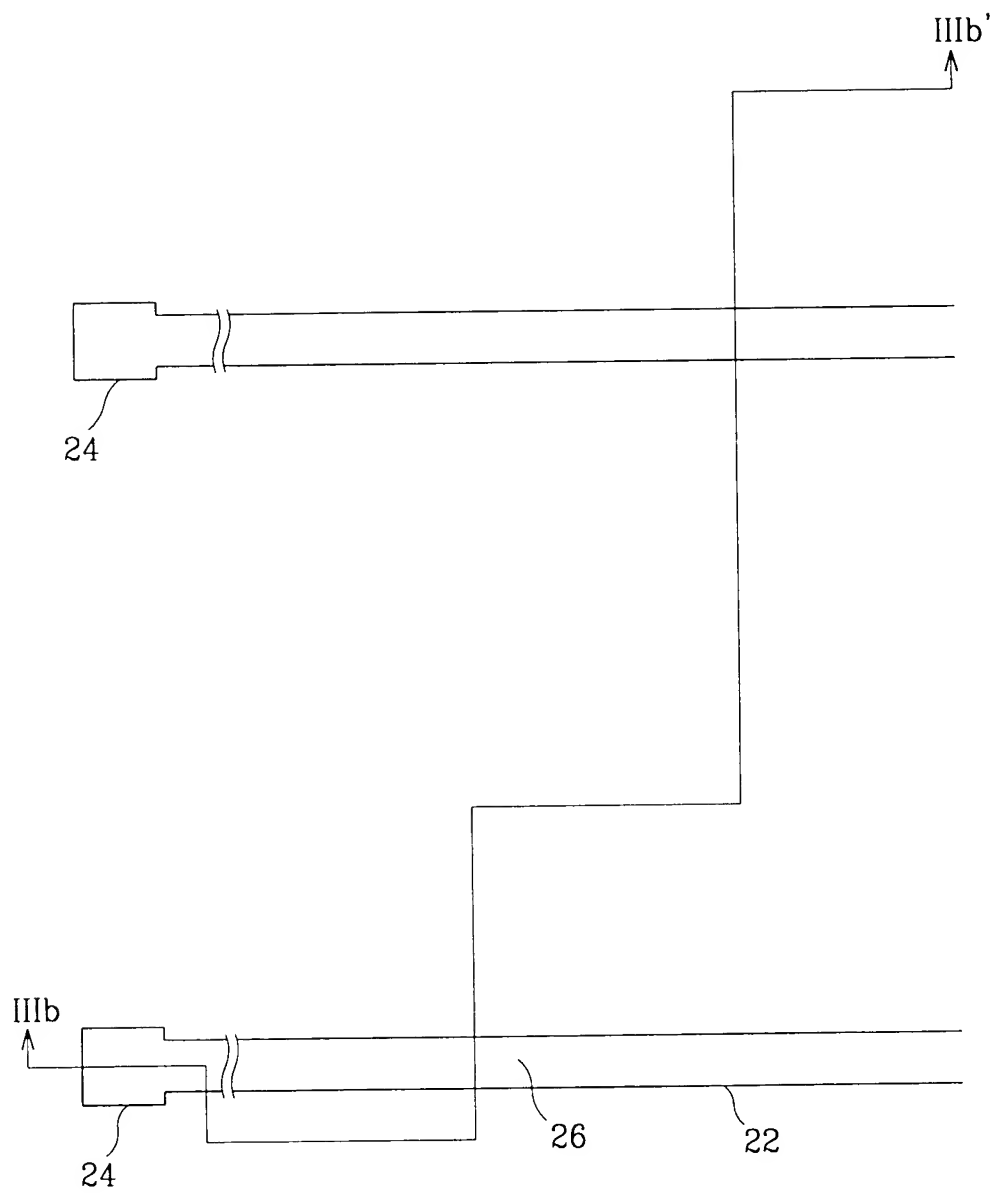


FIG. 3B

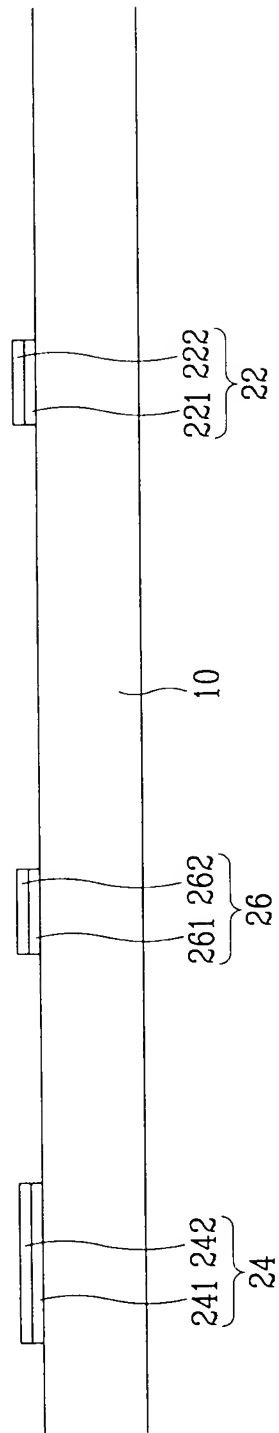


FIG. 4A

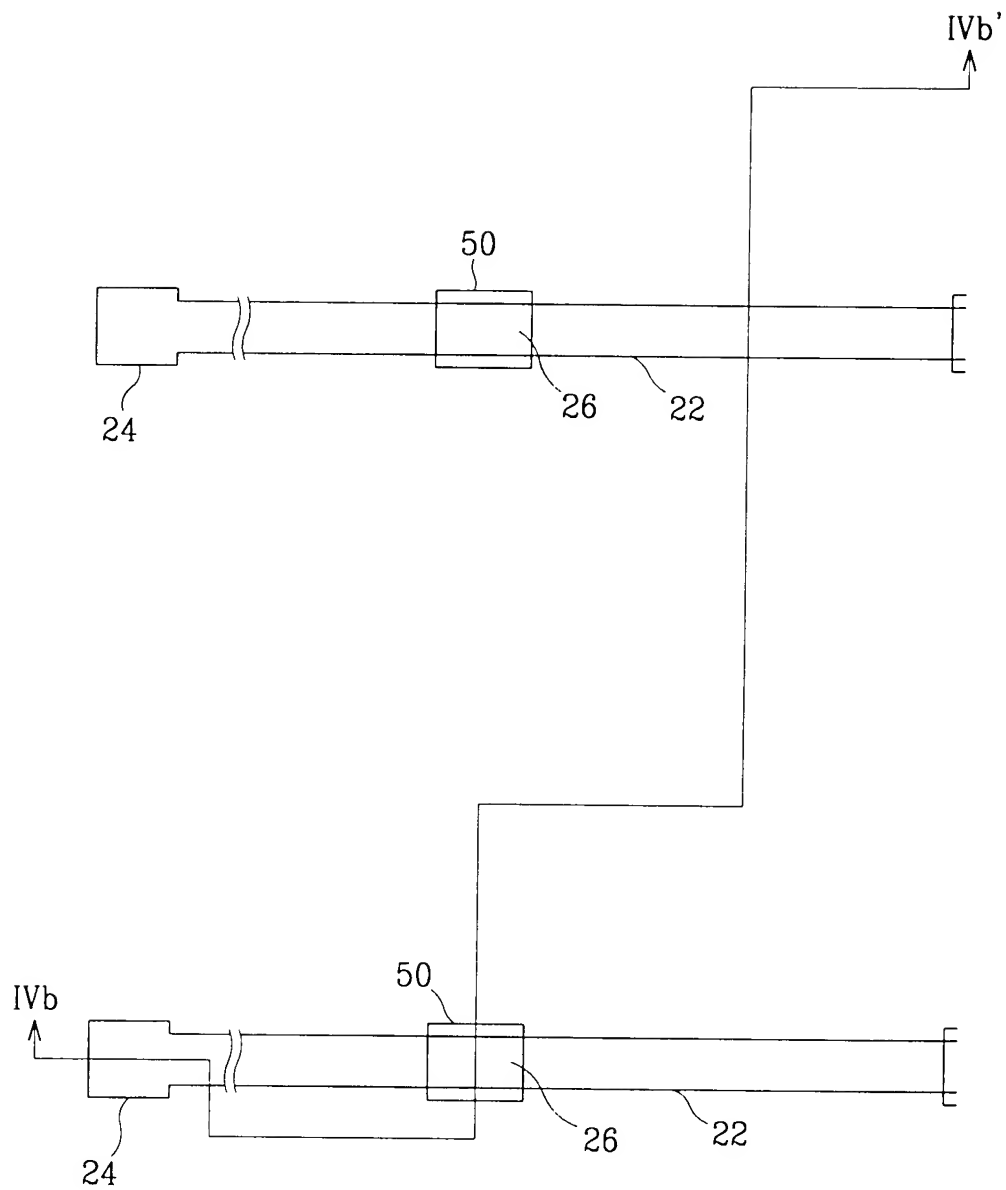
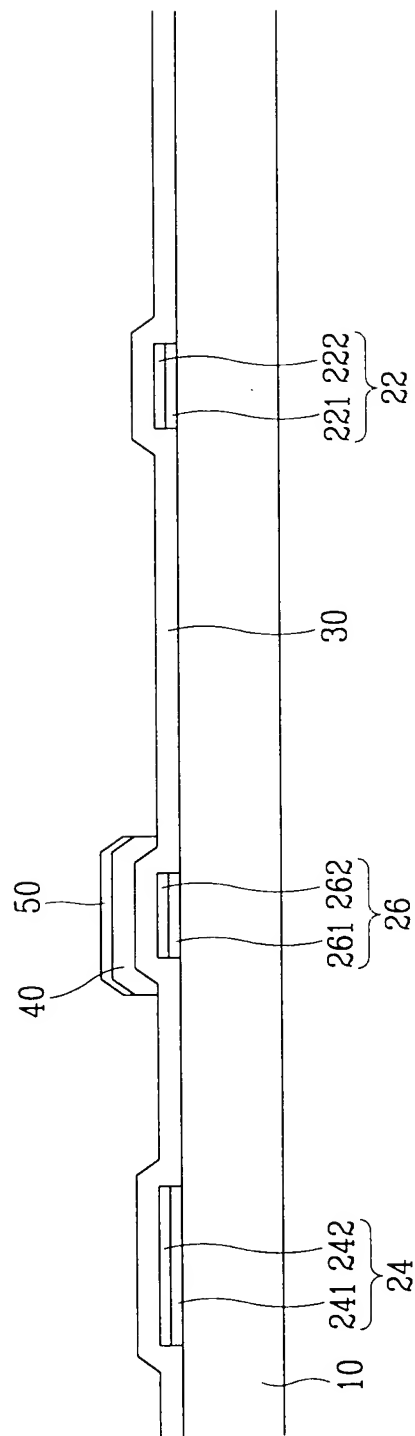


FIG. 4B



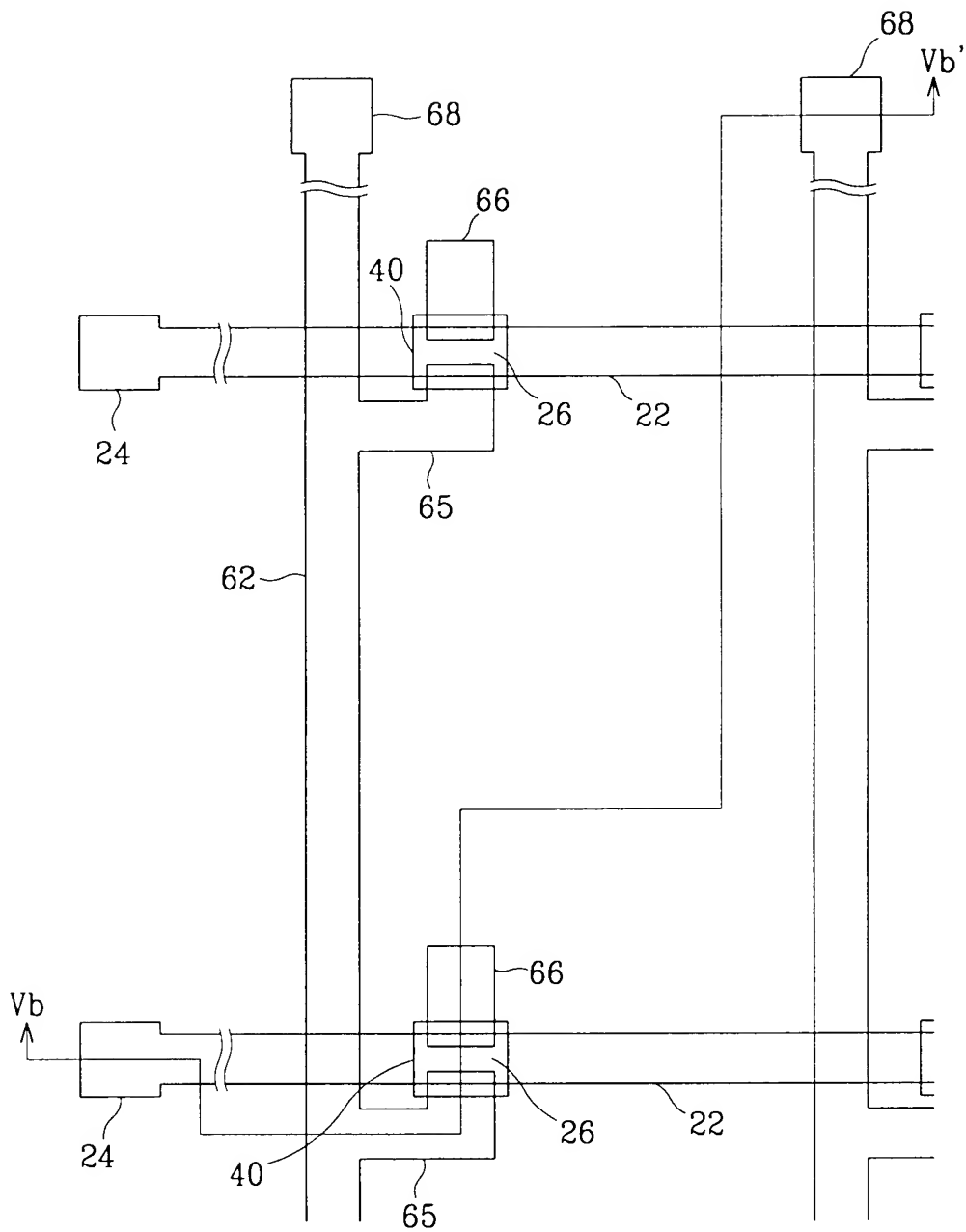
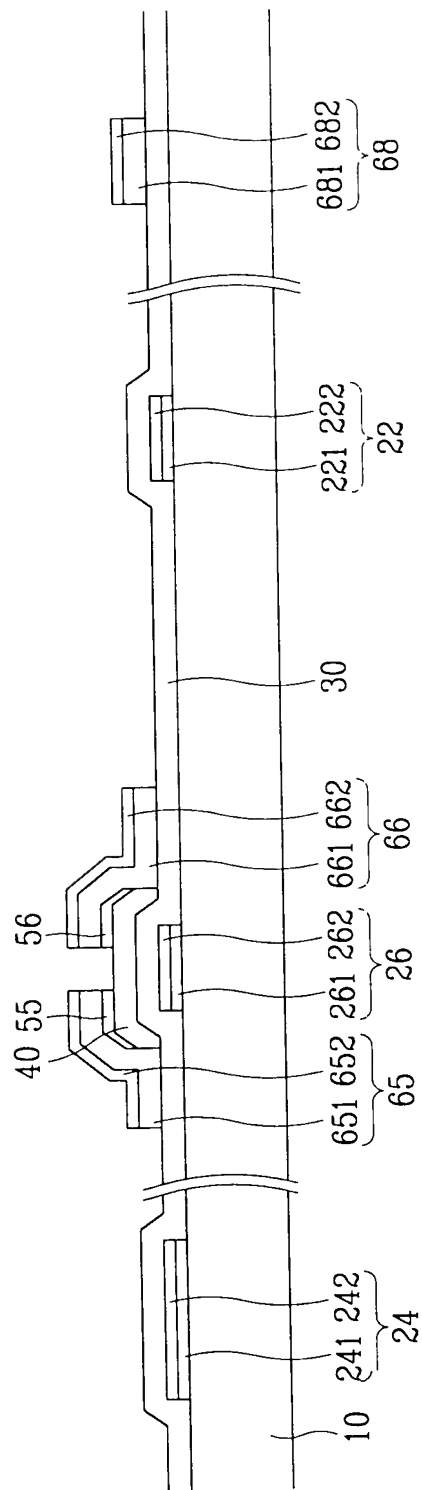


FIG. 5B



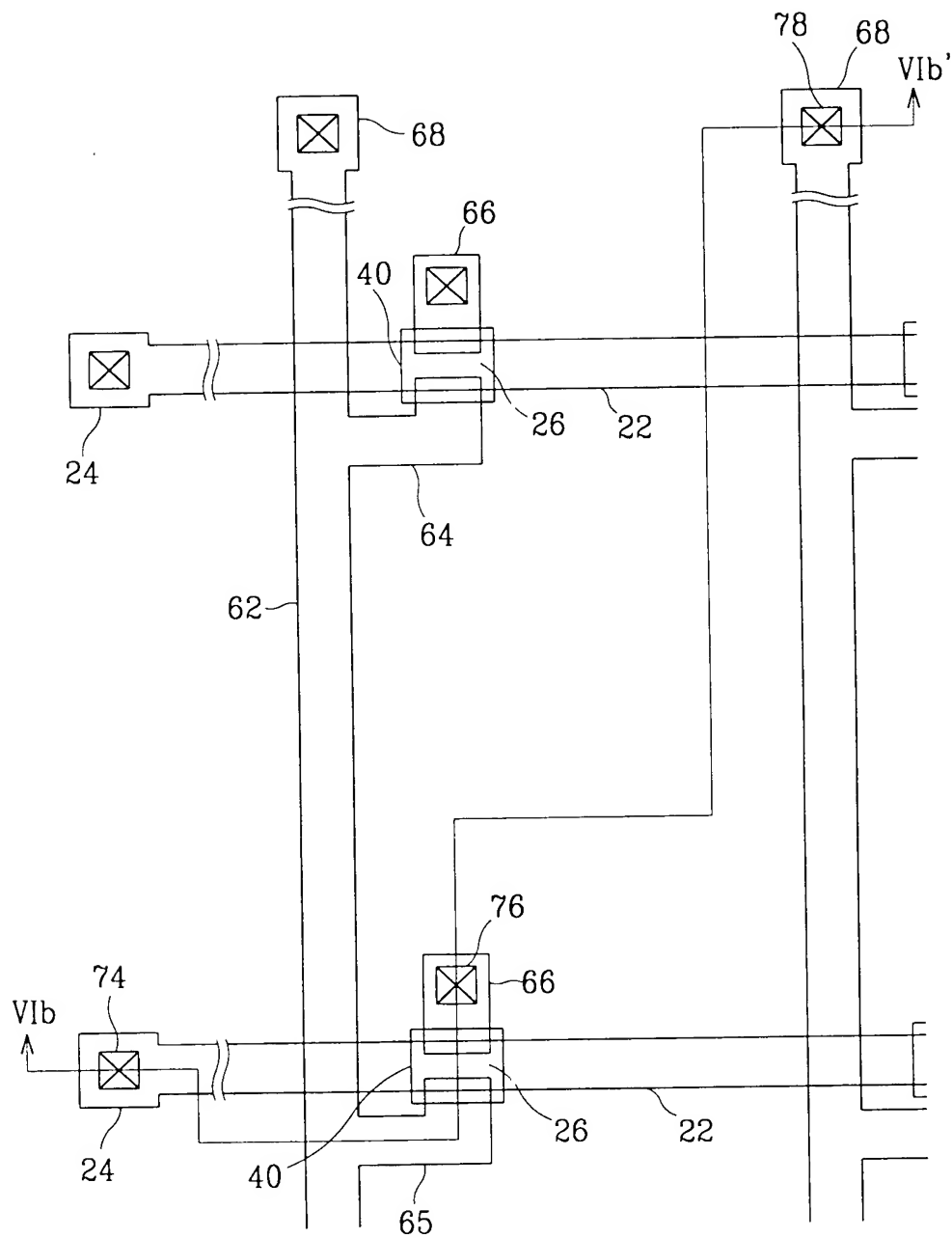


FIG. 6B

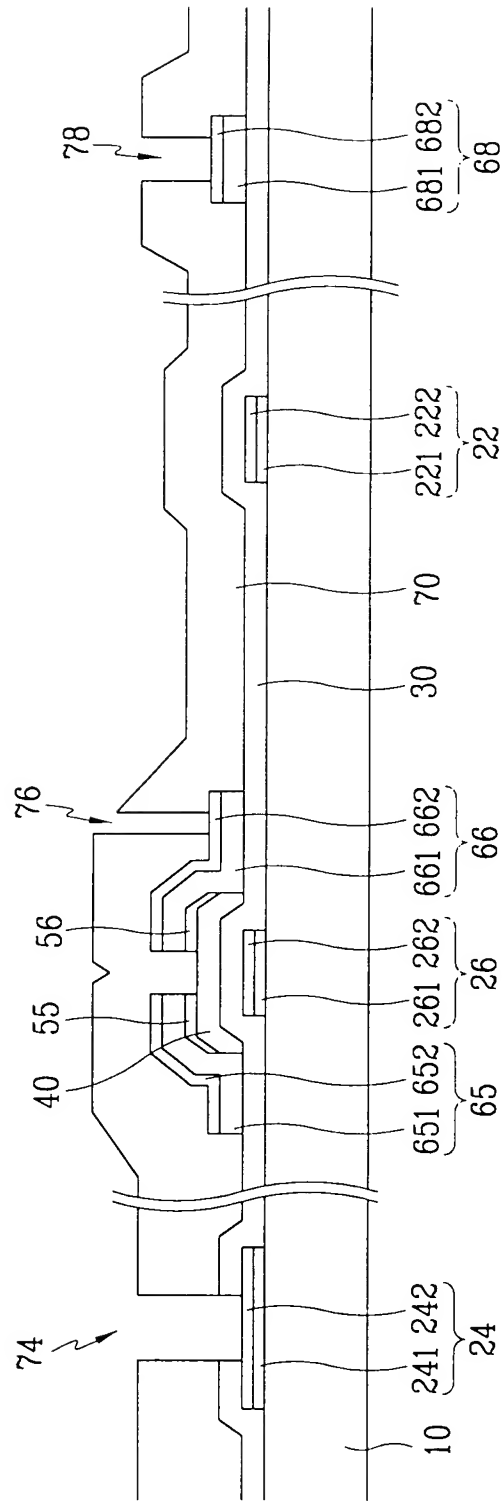


FIG. 7

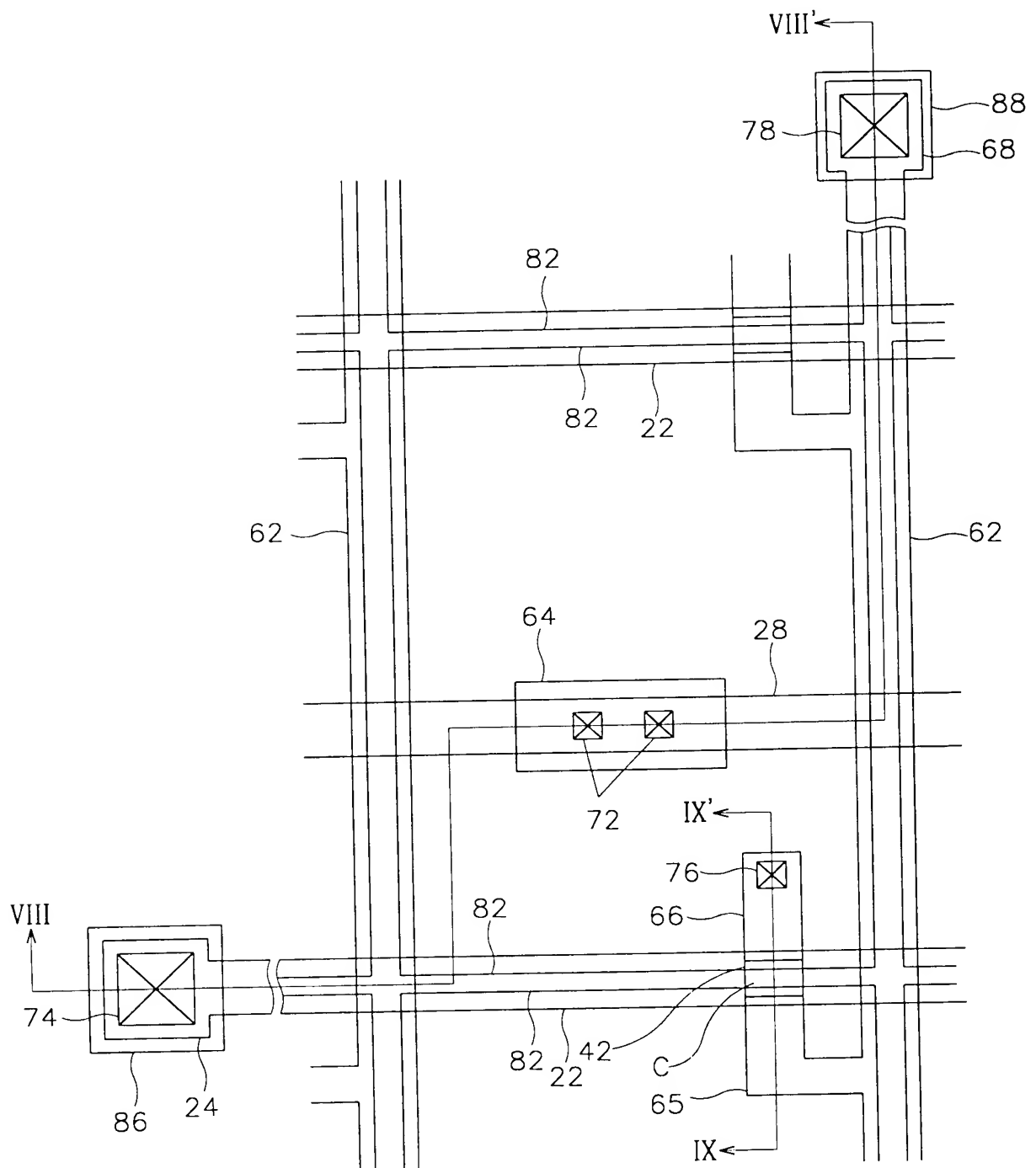


FIG. 8

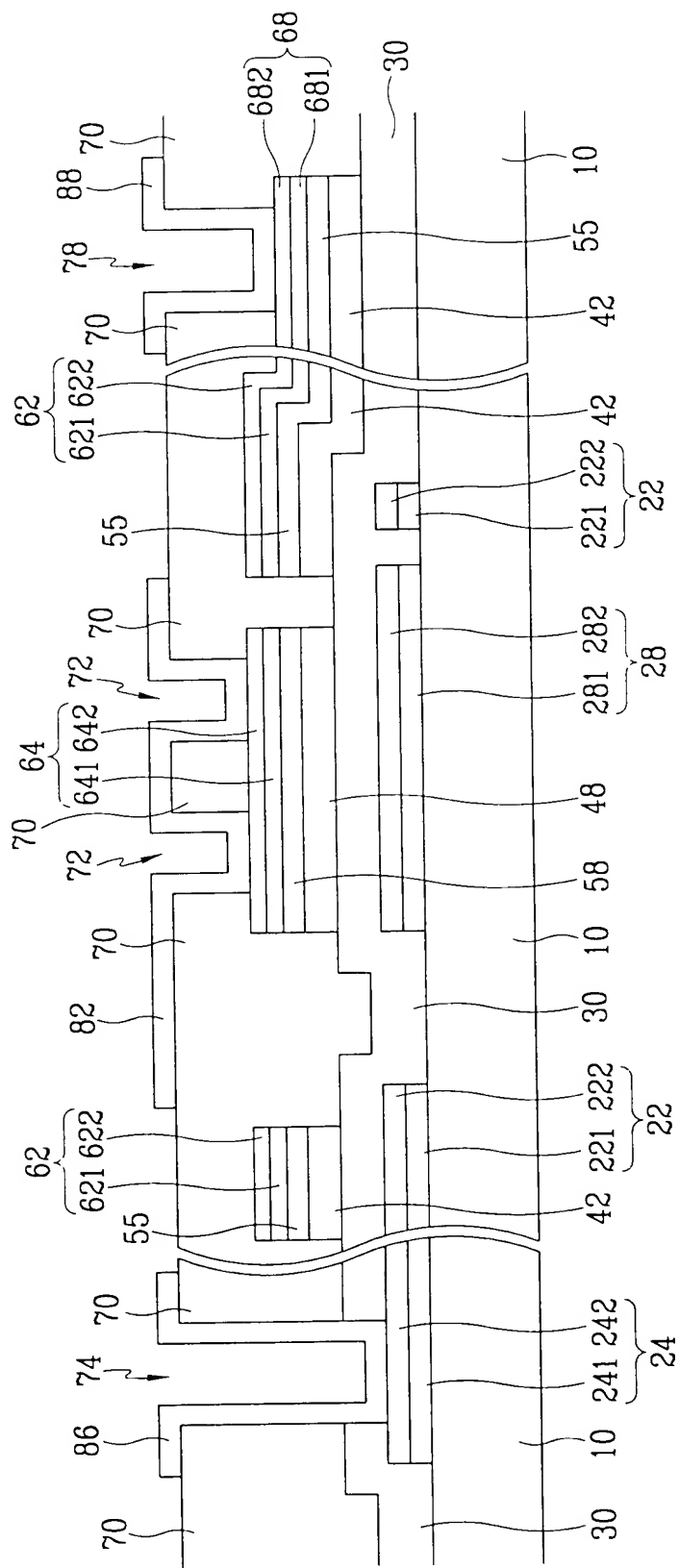


FIG. 9

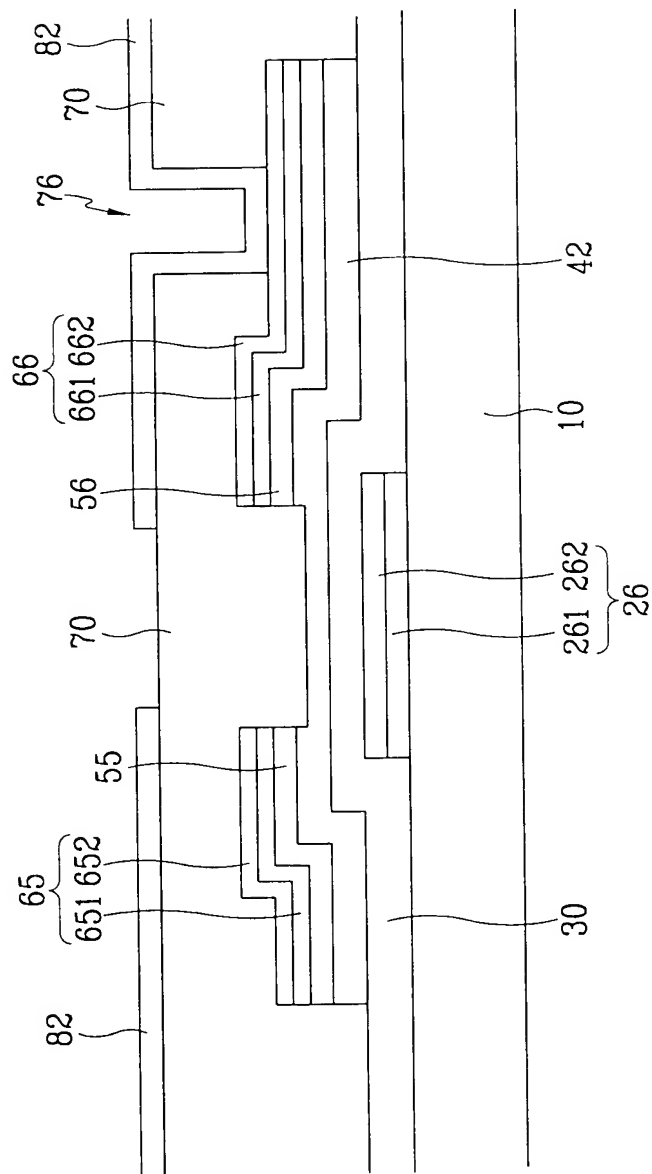


FIG.10A

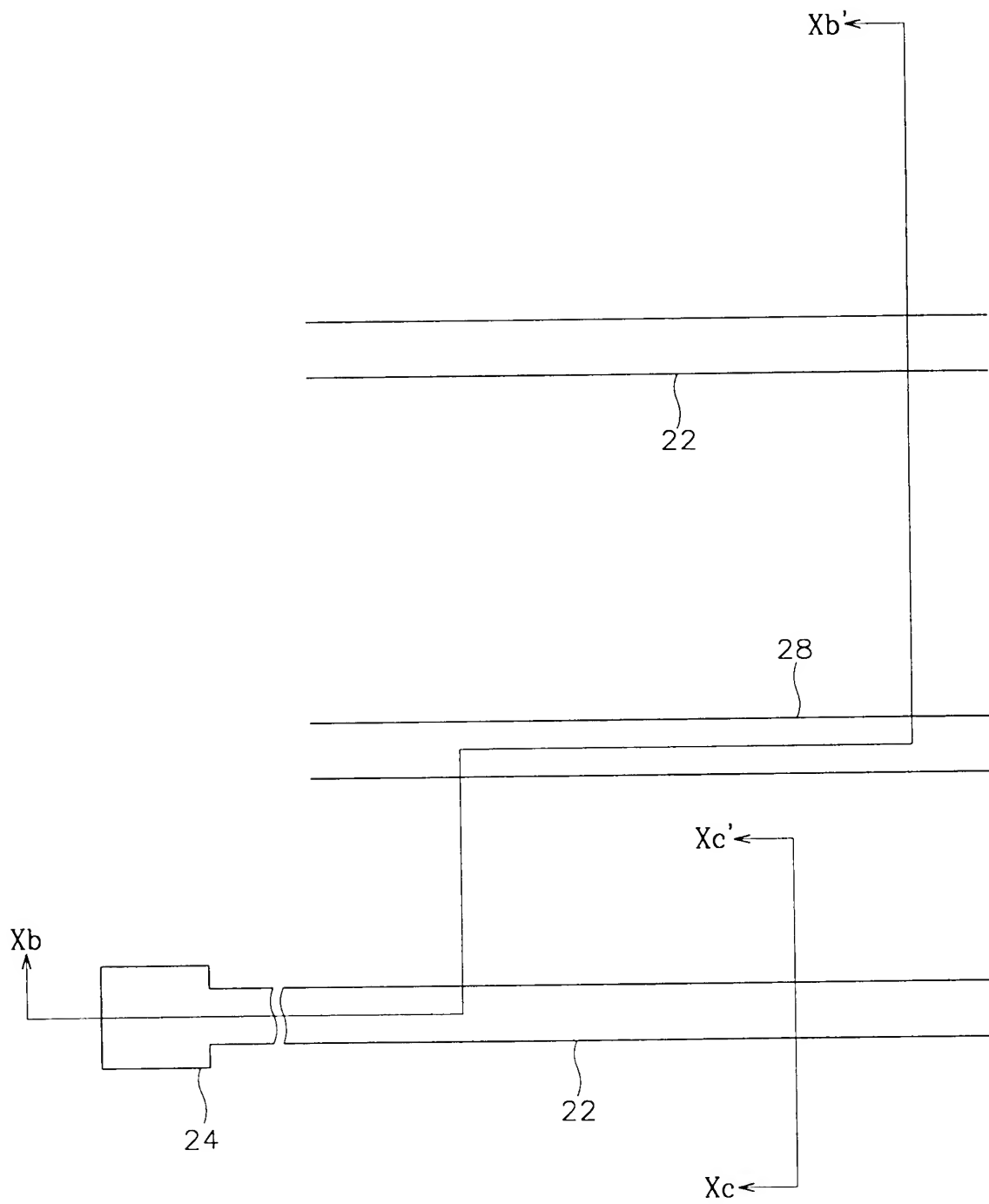


FIG.10B

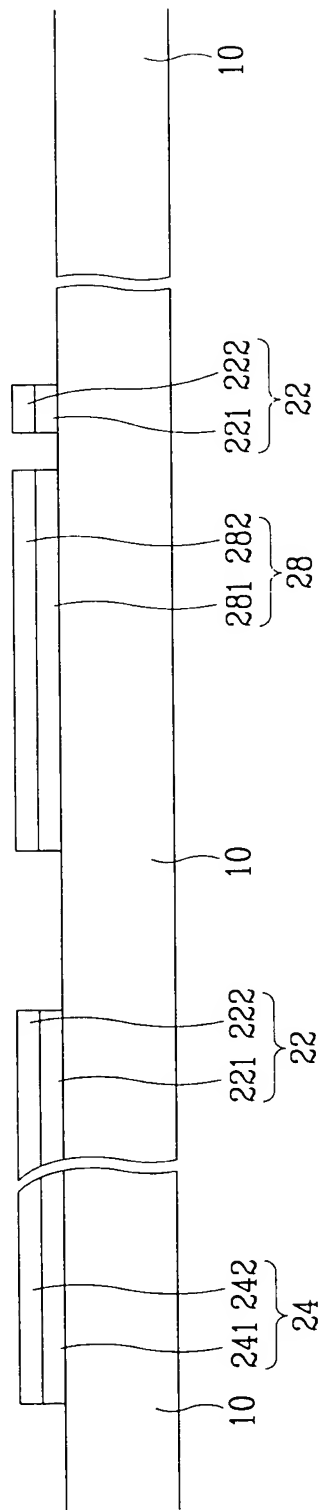


FIG.10C

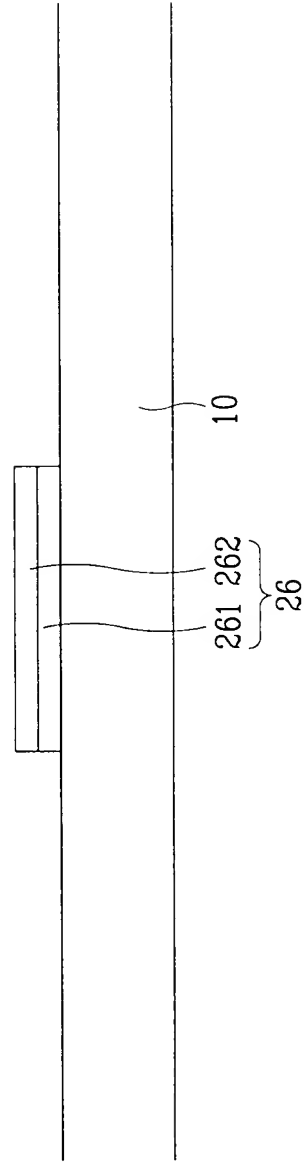


FIG. 11A

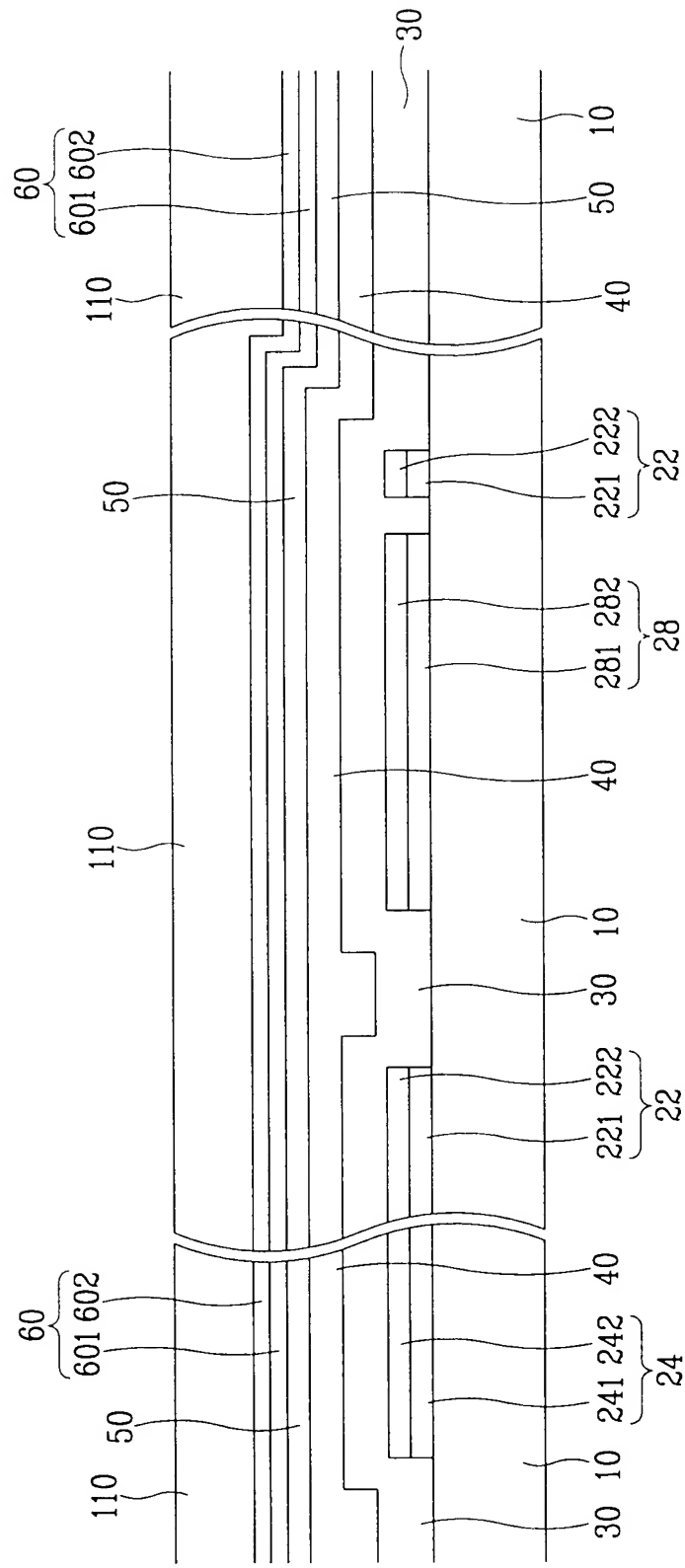


FIG. 11B

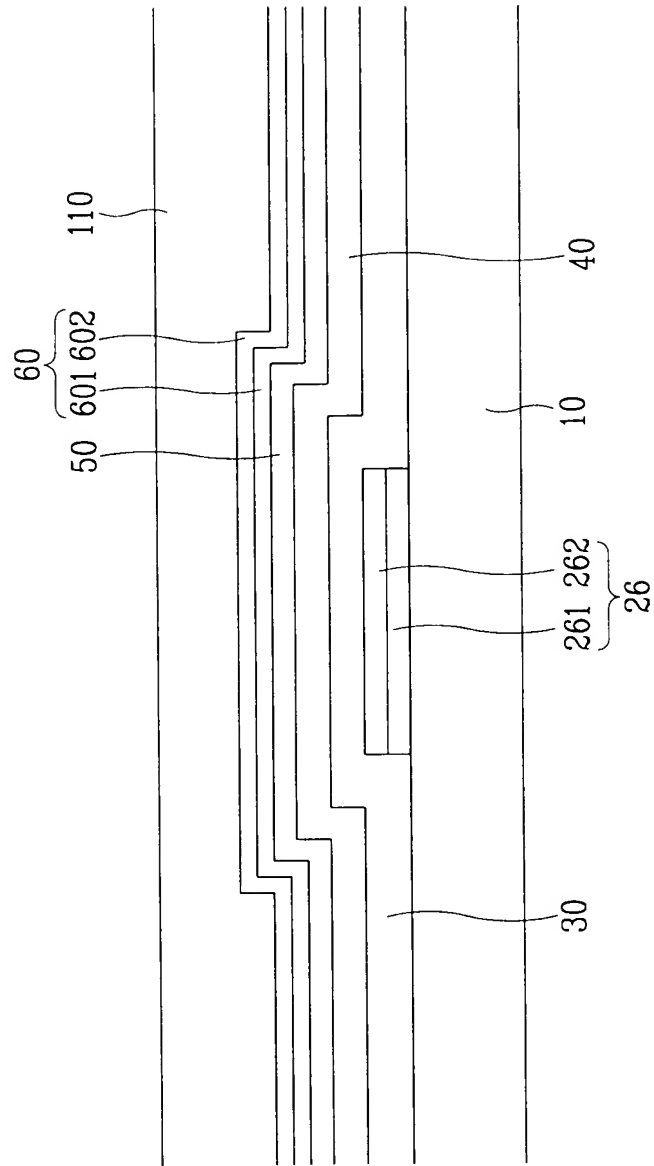


FIG.12A

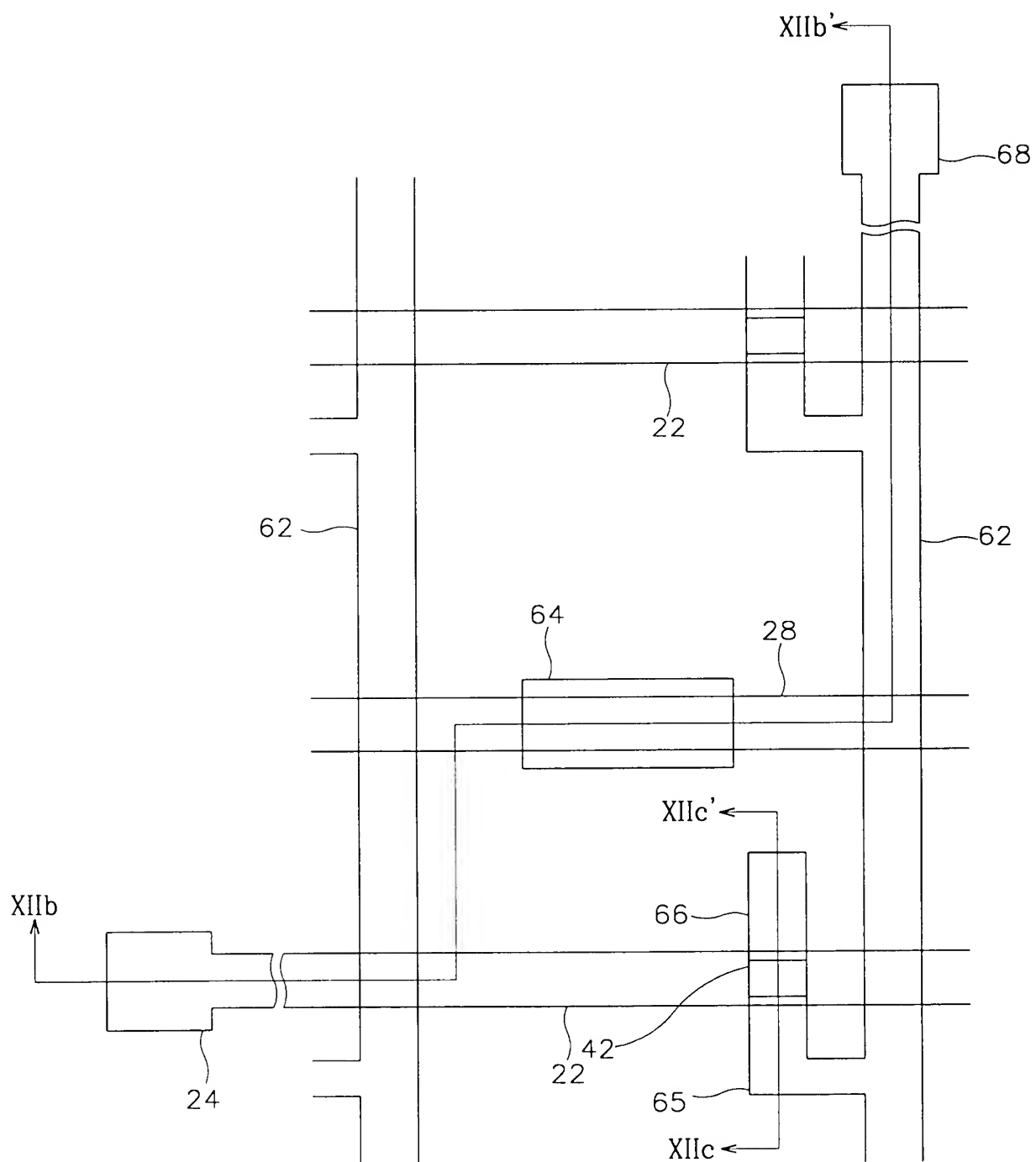


FIG. 12B

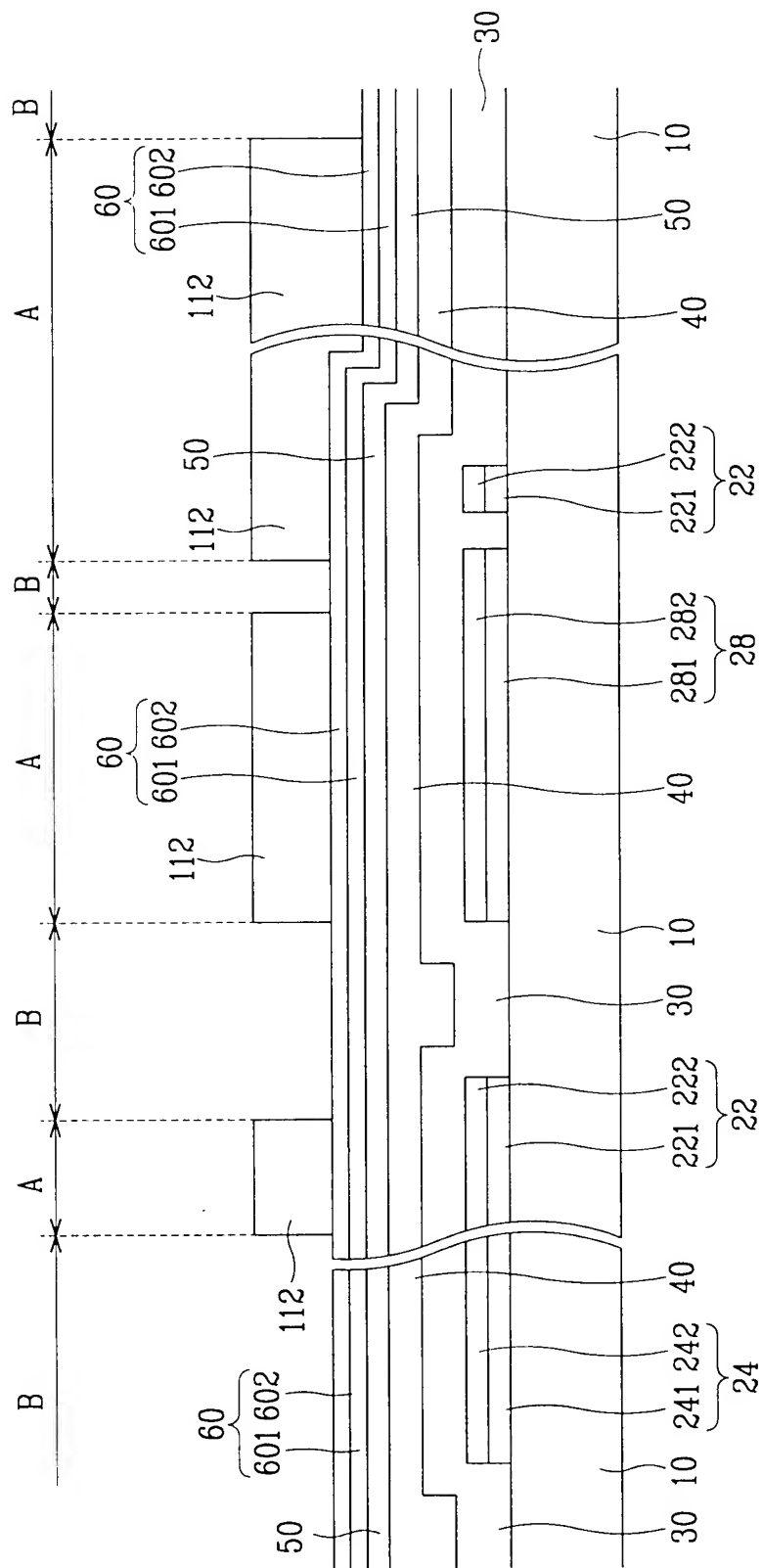
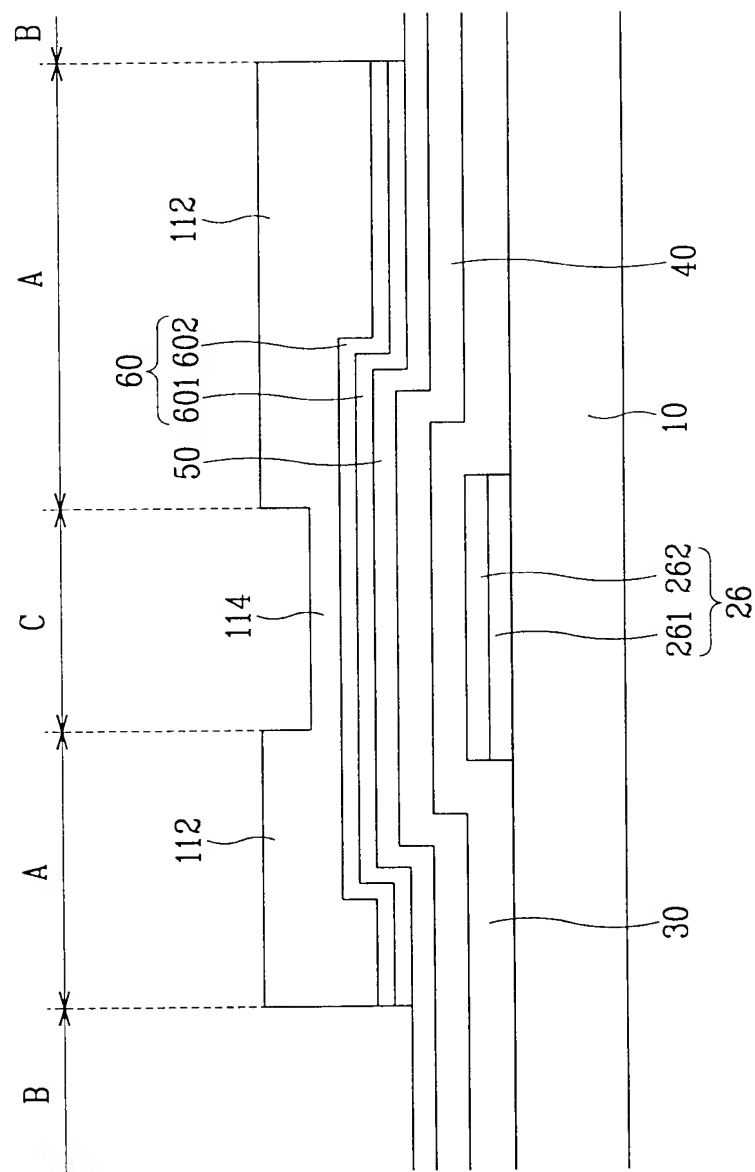
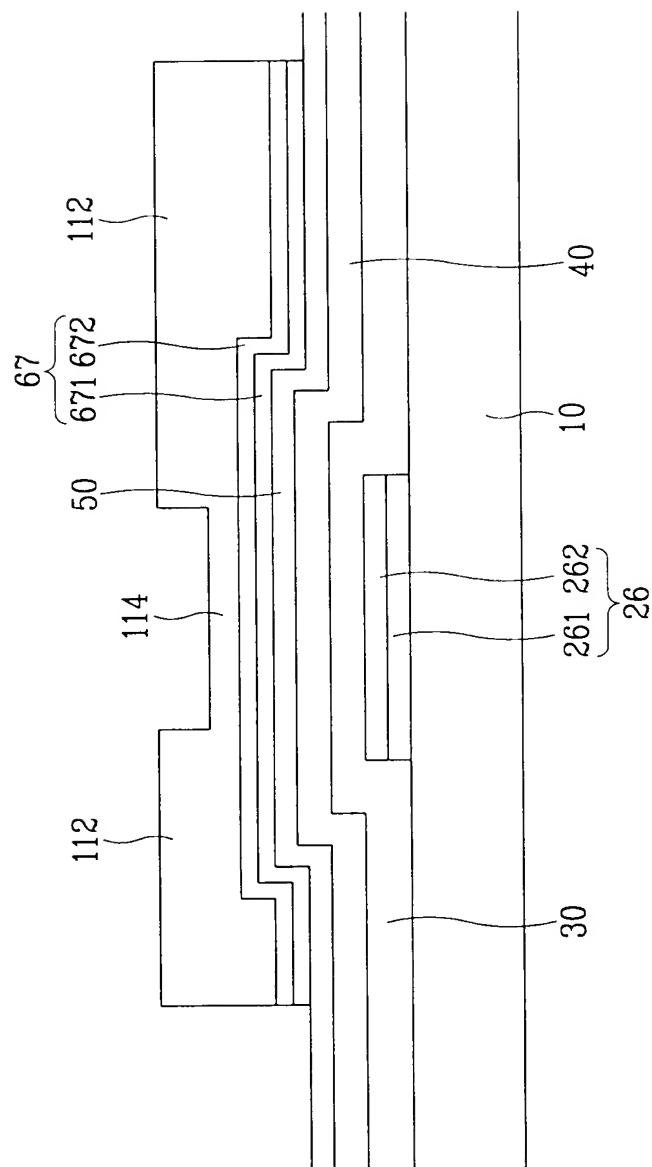


FIG. 12C







This diagram shows a cross-sectional view of a semiconductor device. The device consists of a substrate 10 with a series of layers and regions. From left to right, the structure includes: a first region 24 with layers 241 and 242; a second region 22 with layers 42, 221, and 222; a third region 28 with layers 281 and 282; a fourth region 48 with layer 48; a fifth region 58 with layer 58; a sixth region 30 with layer 30; a seventh region 10 with layer 10; an eighth region 57 with layer 57; and a ninth region 64 with layers 641 and 642. A final region 67 is shown on the far right, containing layers 671 and 672. The layers 10, 241, 242, 42, 221, 222, 281, 282, 48, 58, 30, 57, 641, 642, 671, and 672 are all part of a common layer stack. The regions 24, 22, 28, 48, 58, 30, 57, and 64 are defined by the boundaries of these layers. The regions 10, 22, 28, 48, 58, 30, 57, and 64 are also labeled with reference numerals 10, 22, 28, 48, 58, 30, 57, and 64, respectively. The regions 24, 22, 28, 48, 58, 30, 57, and 64 are also labeled with reference numerals 24, 22, 28, 48, 58, 30, 57, and 64, respectively.

FIG.14B

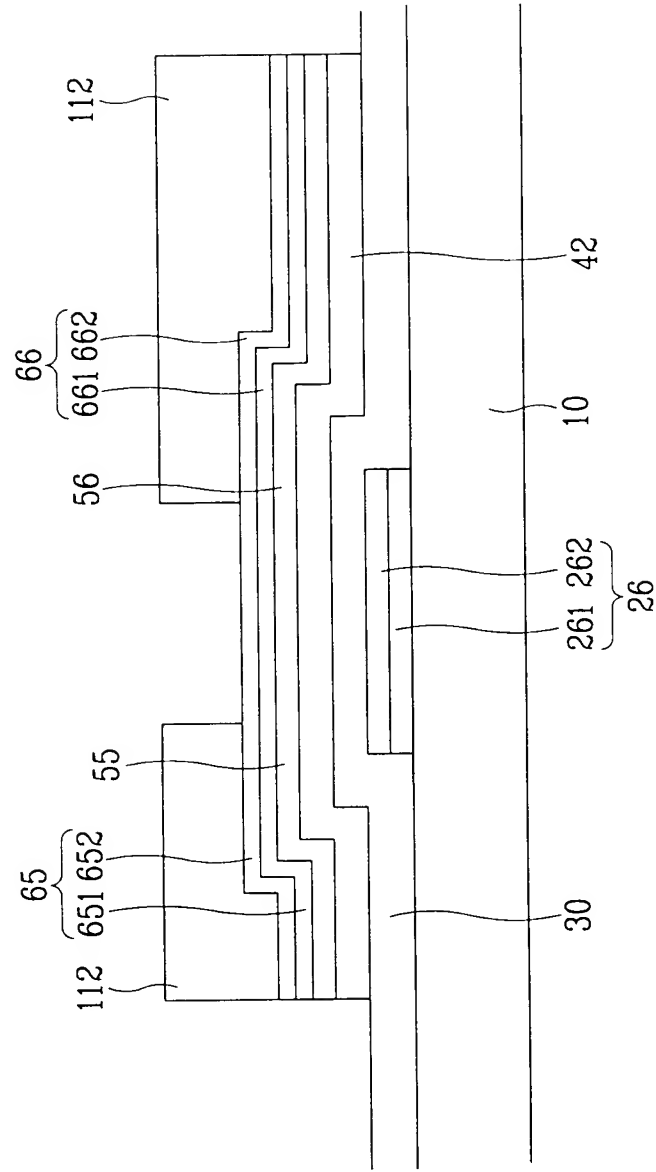


FIG. 15A

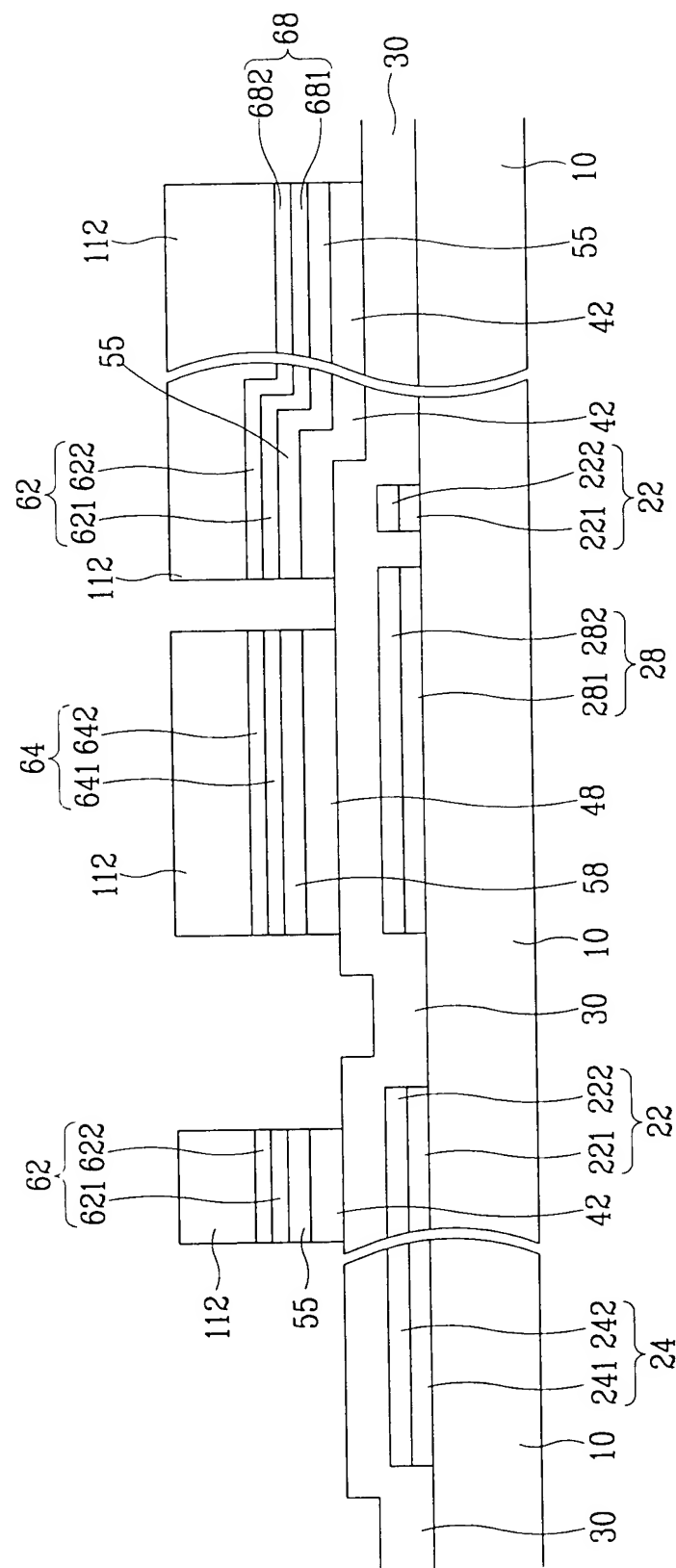


FIG.15B

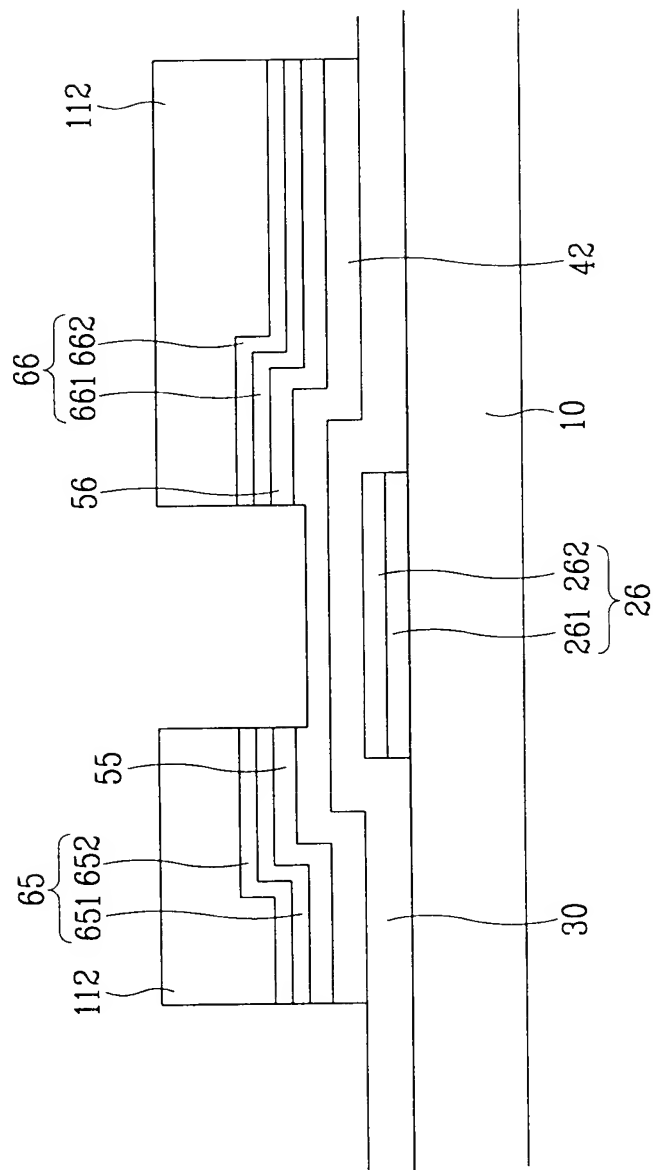


FIG. 16A

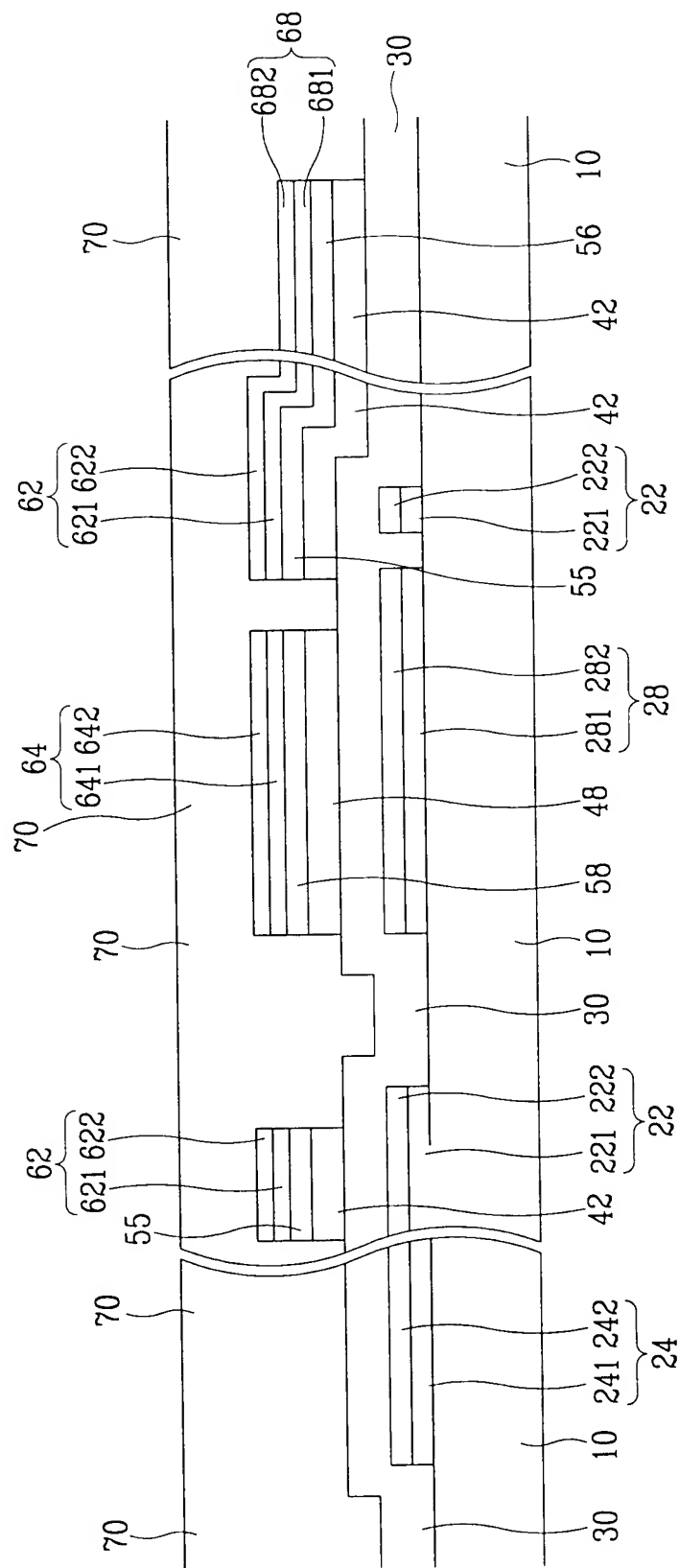


FIG. 16B

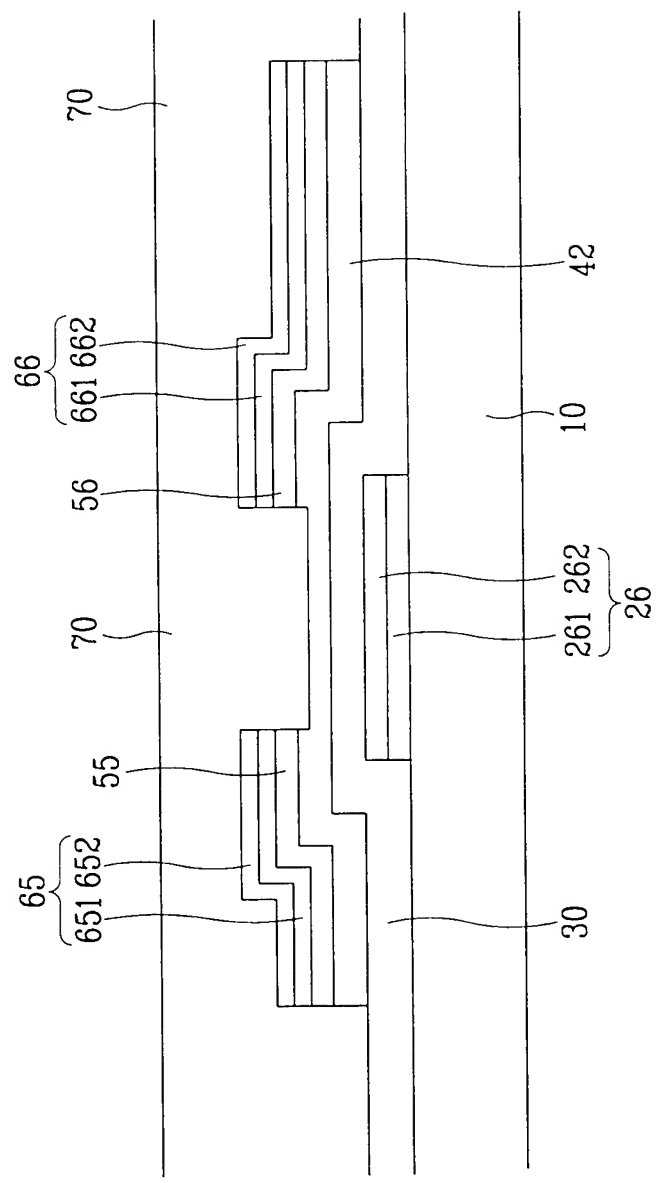


FIG.17A

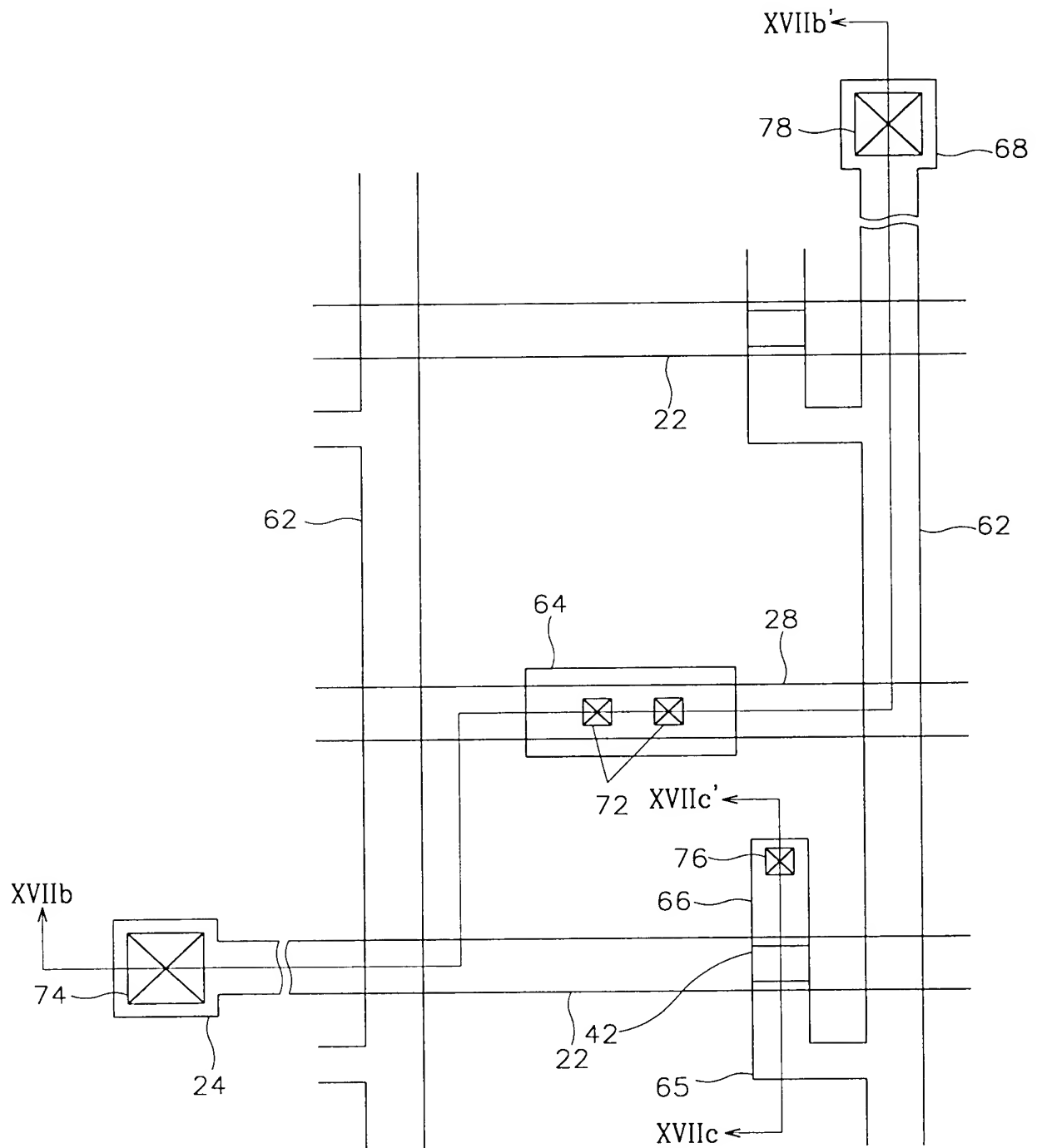


FIG. 17B

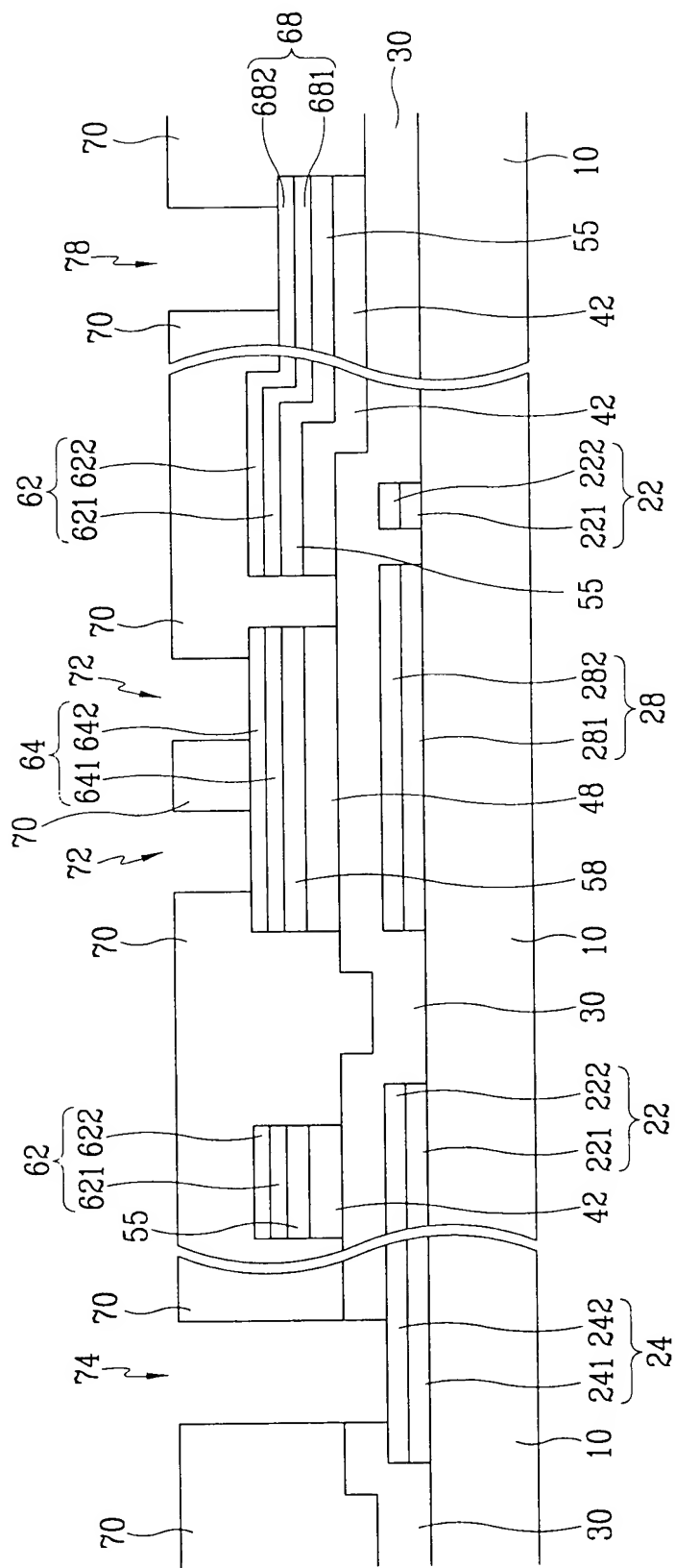


FIG.17C

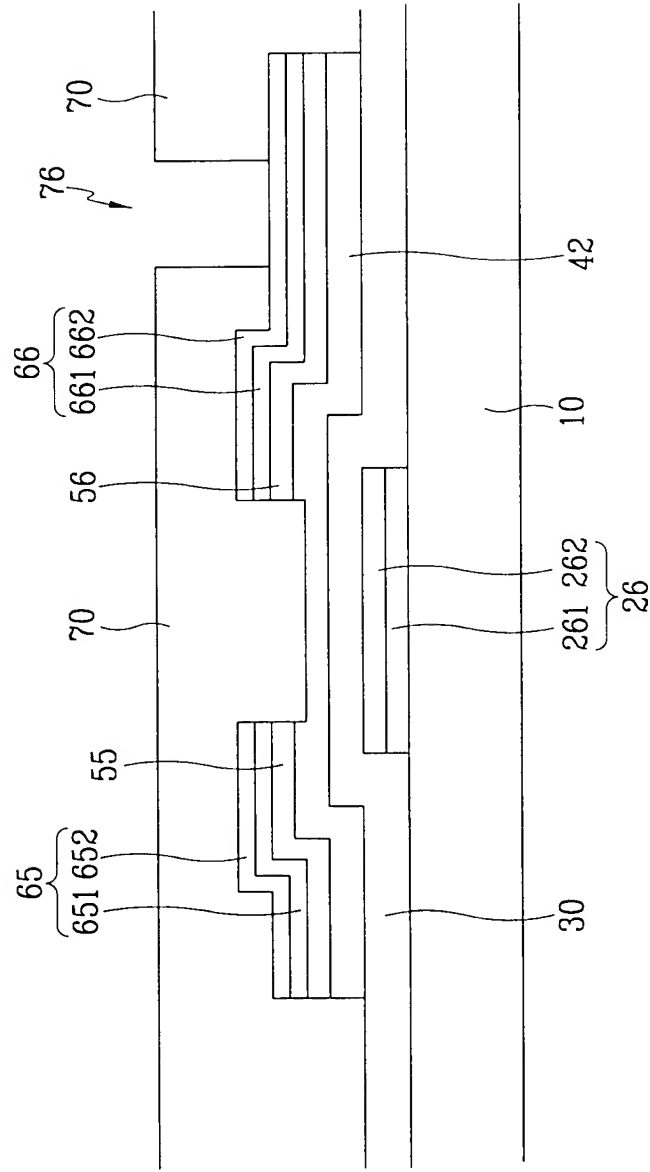


FIG.18

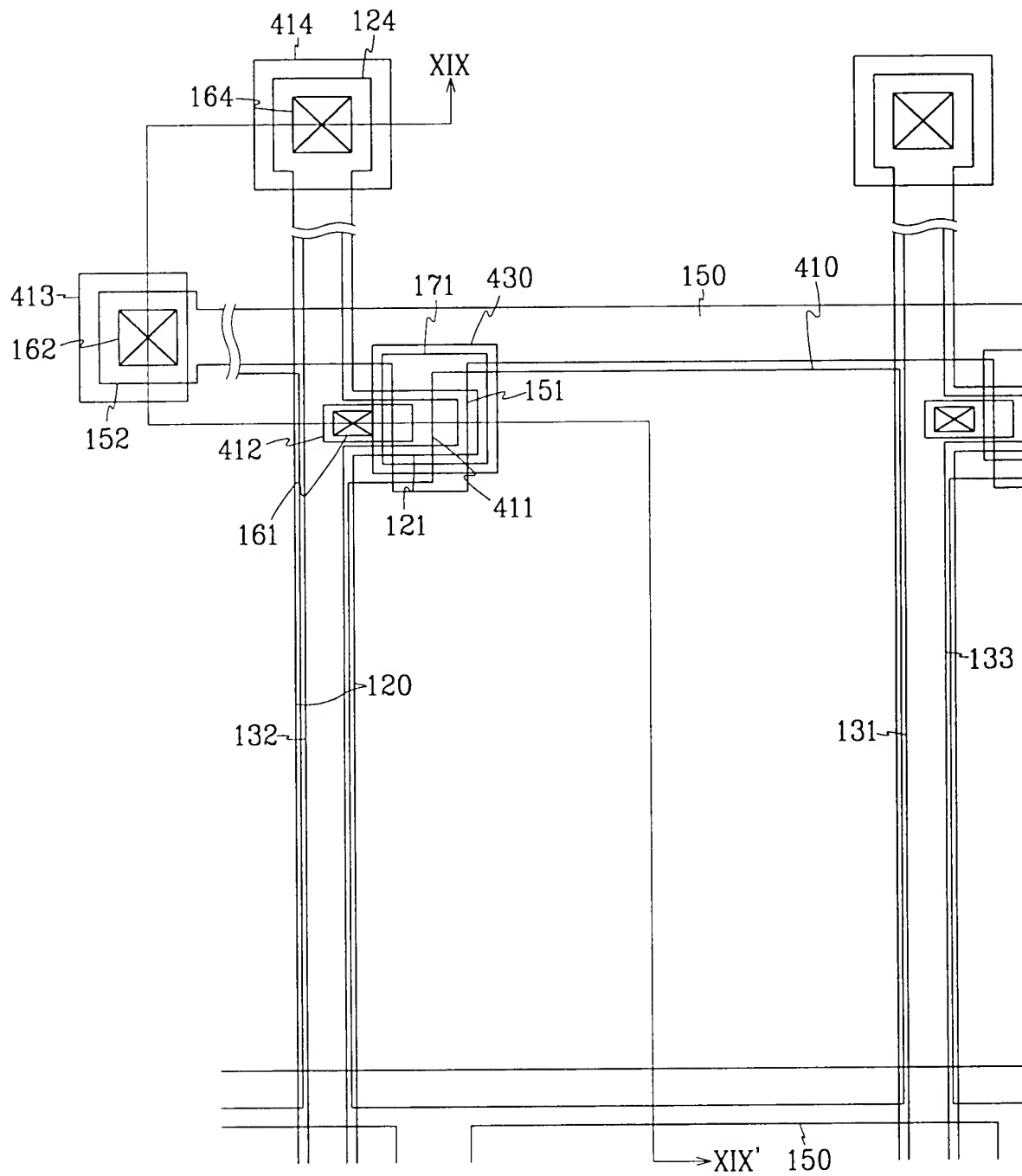


FIG.19

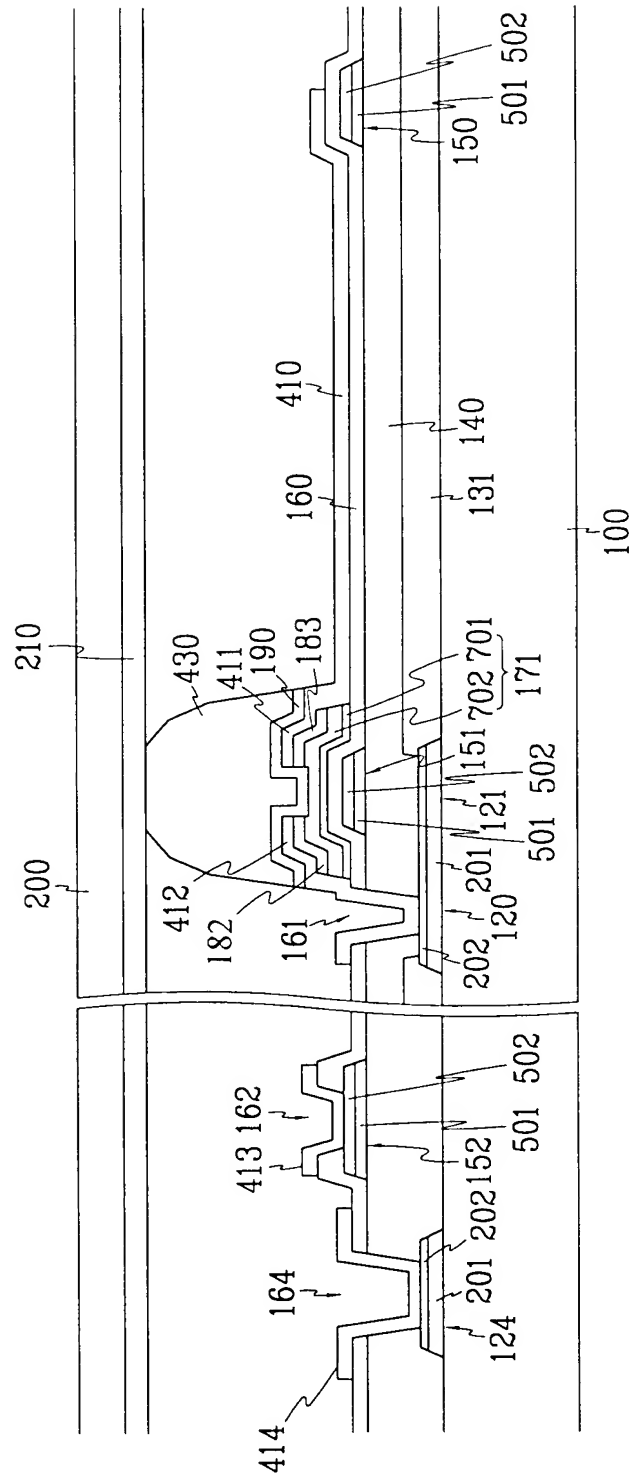


FIG.20A

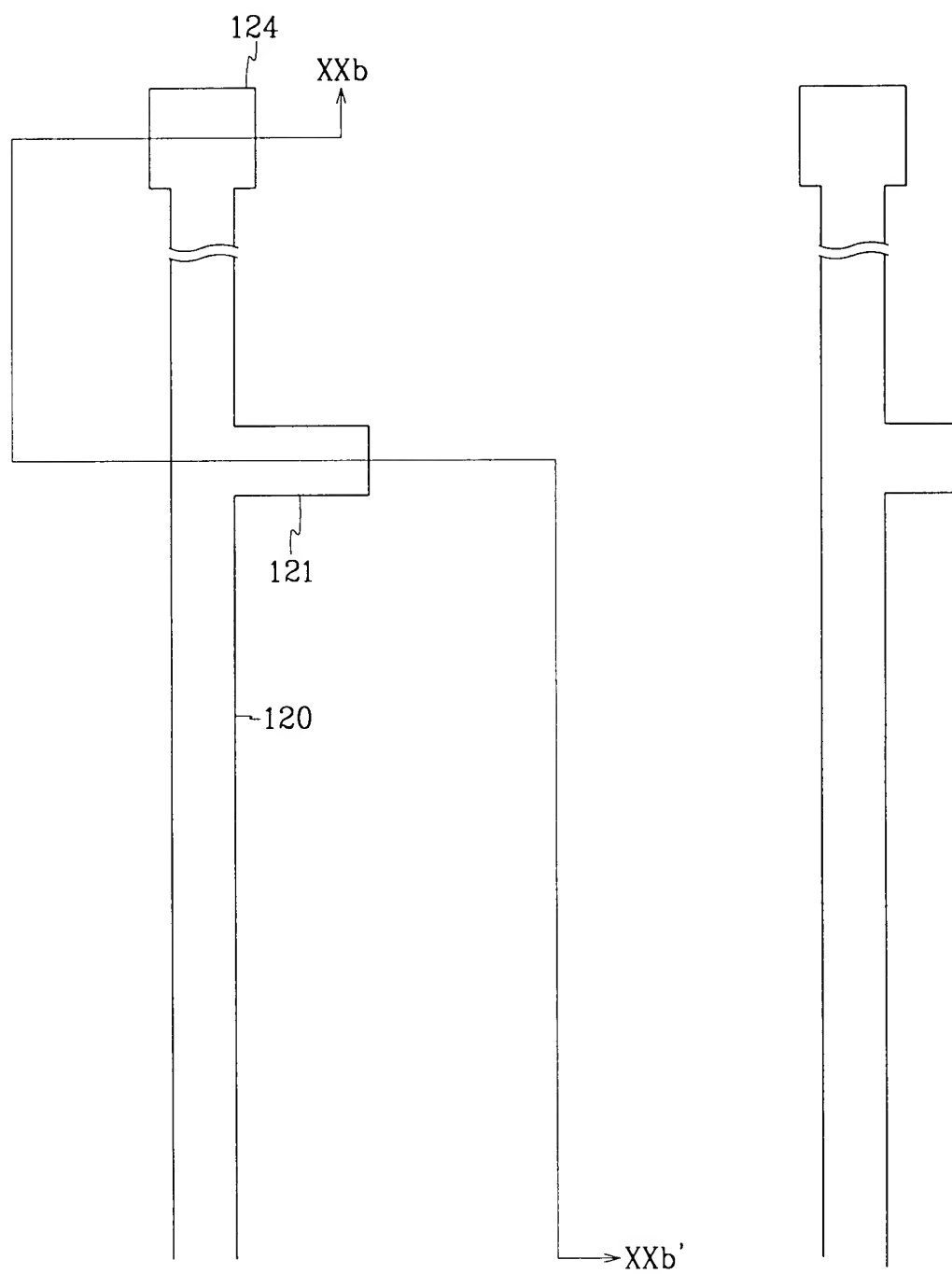


FIG. 20B

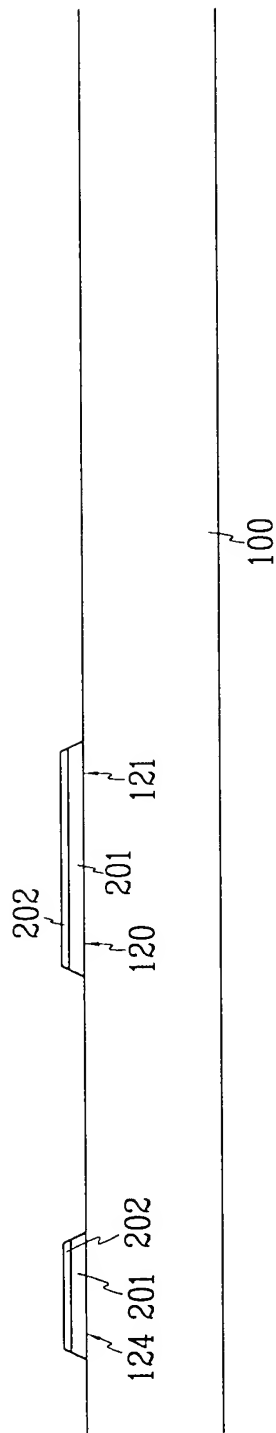


FIG.21A

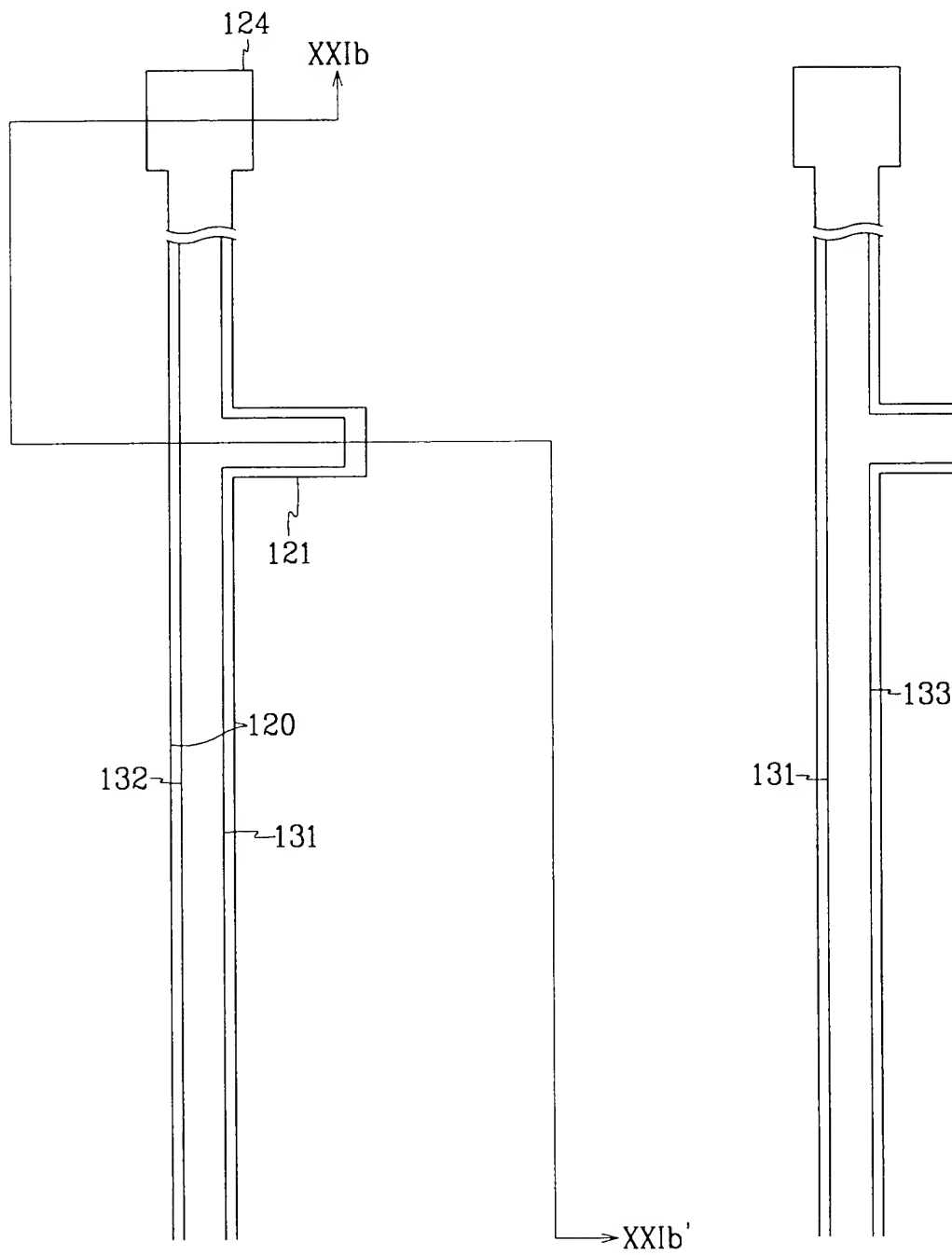
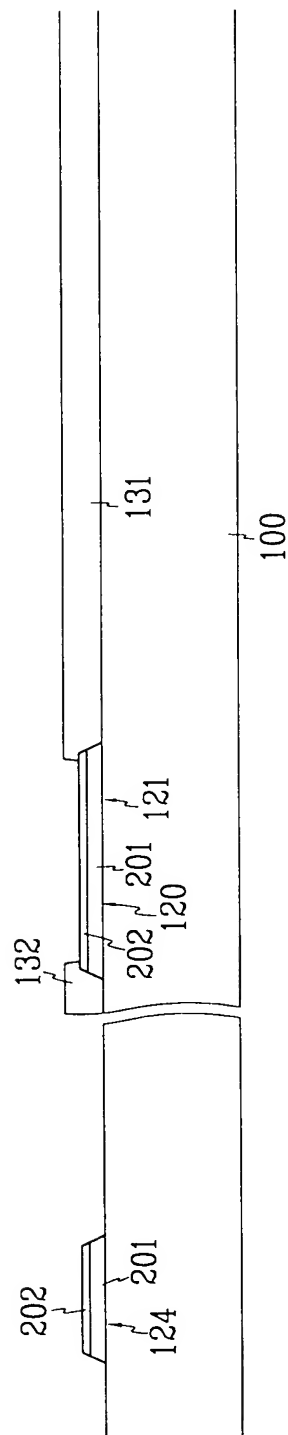


FIG. 21B



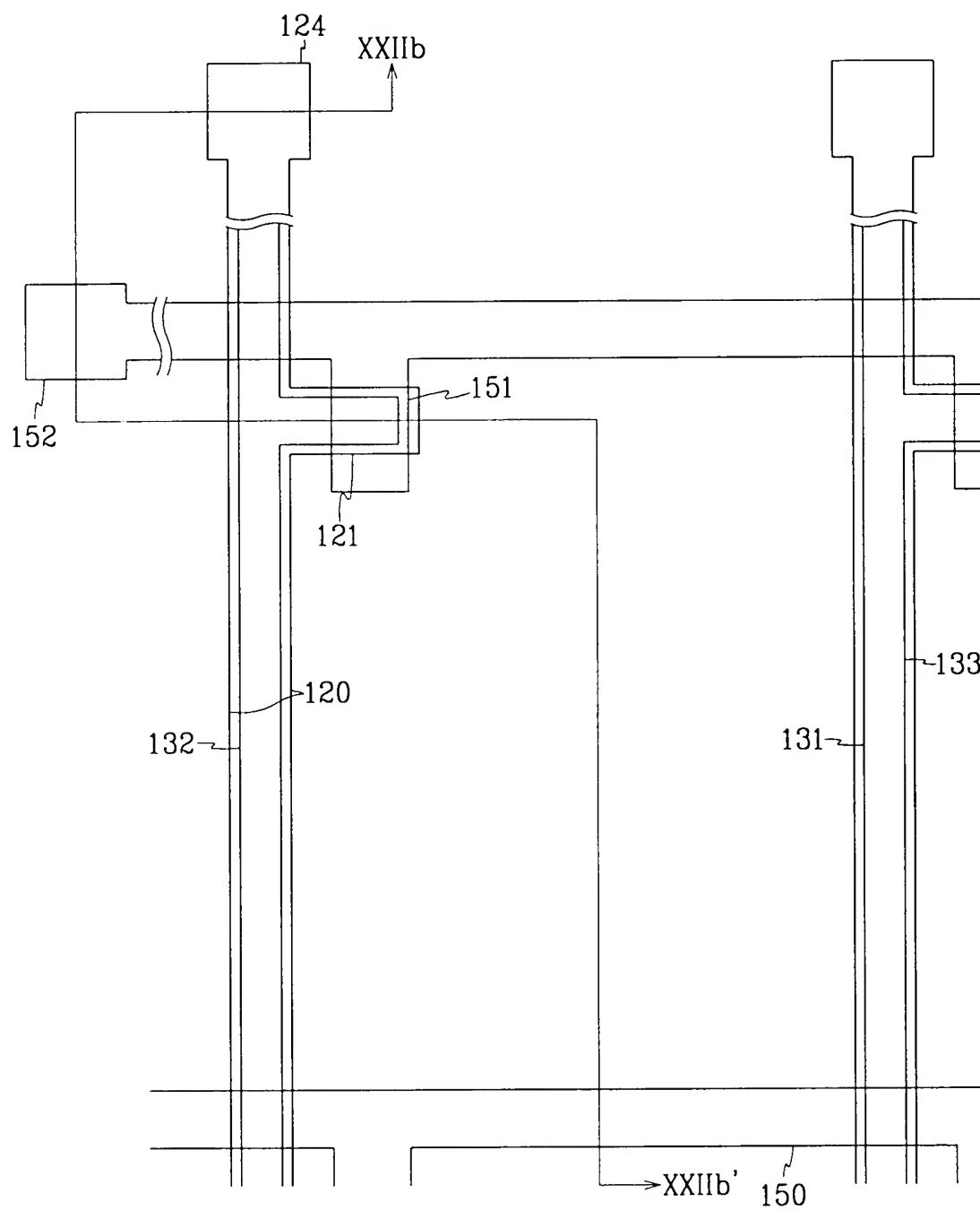


FIG. 22B

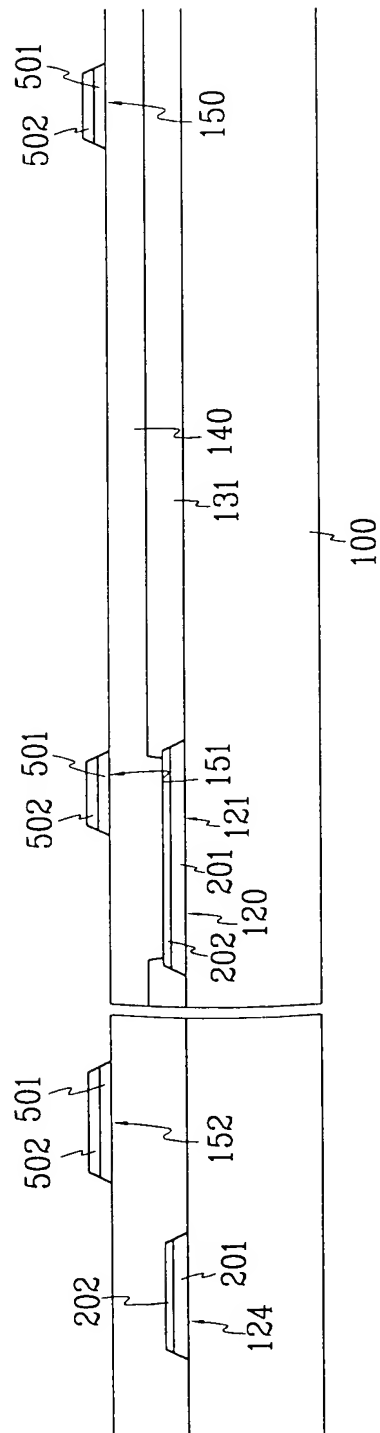


FIG. 23

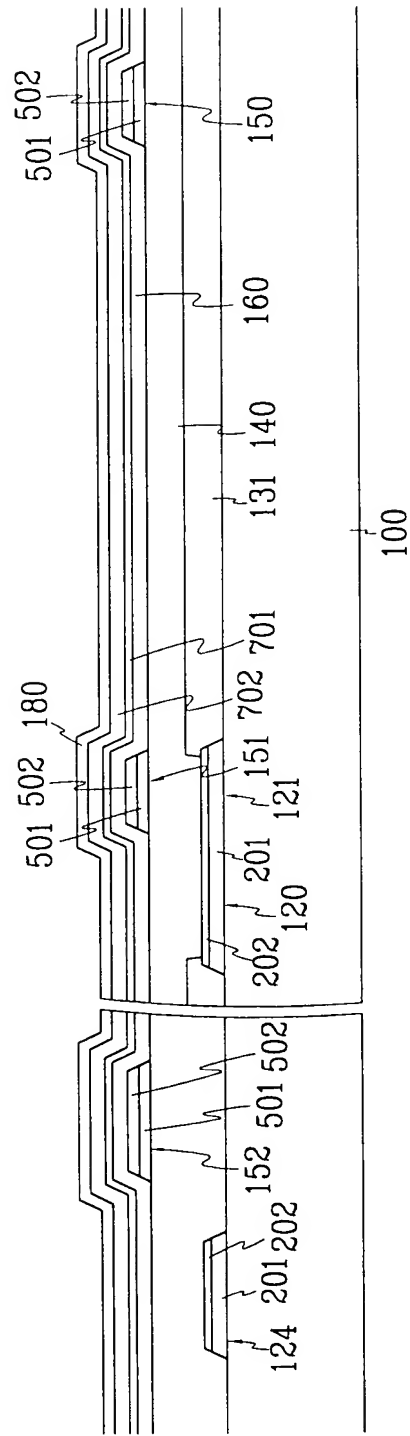


FIG.24A

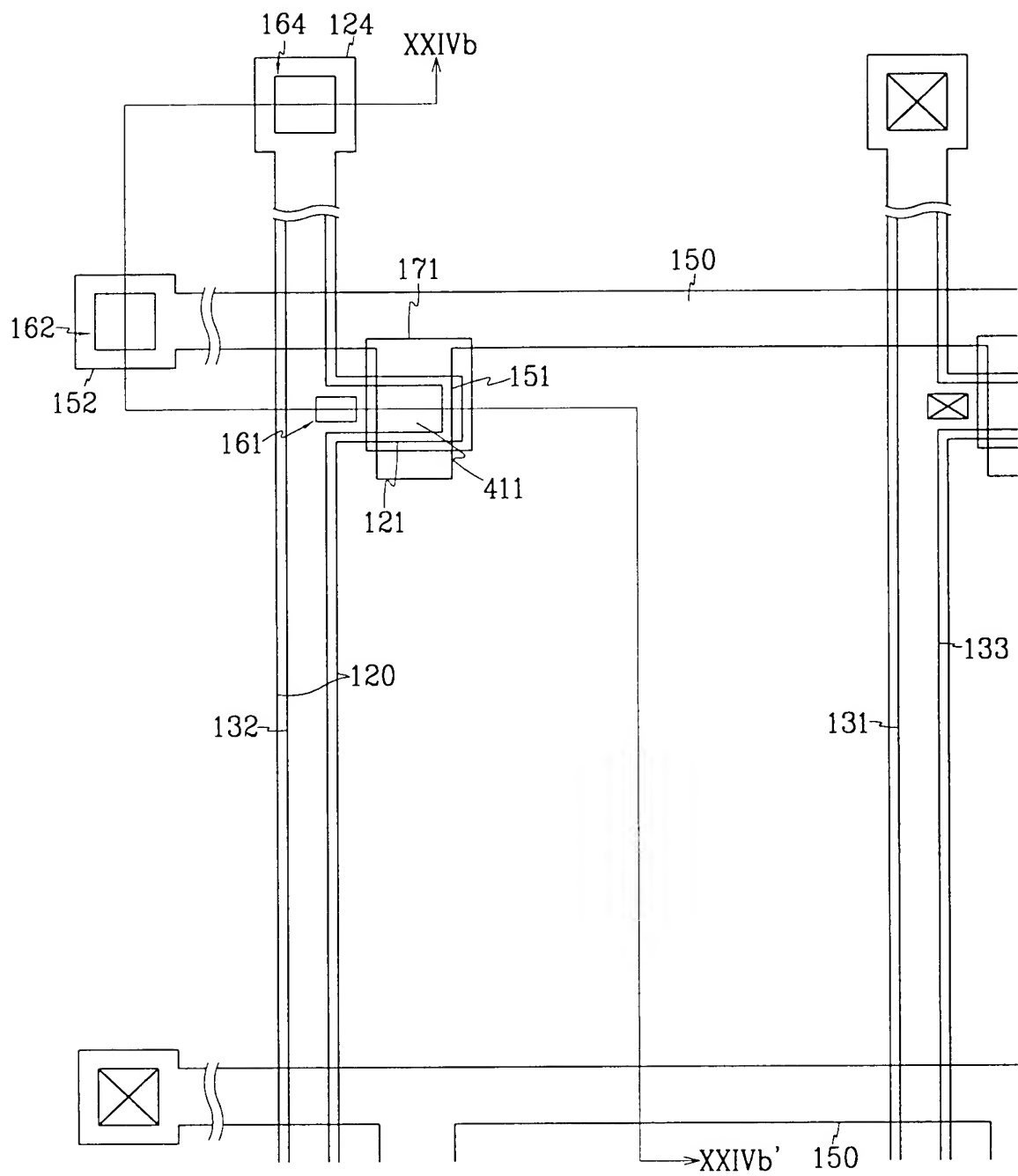


FIG. 24B

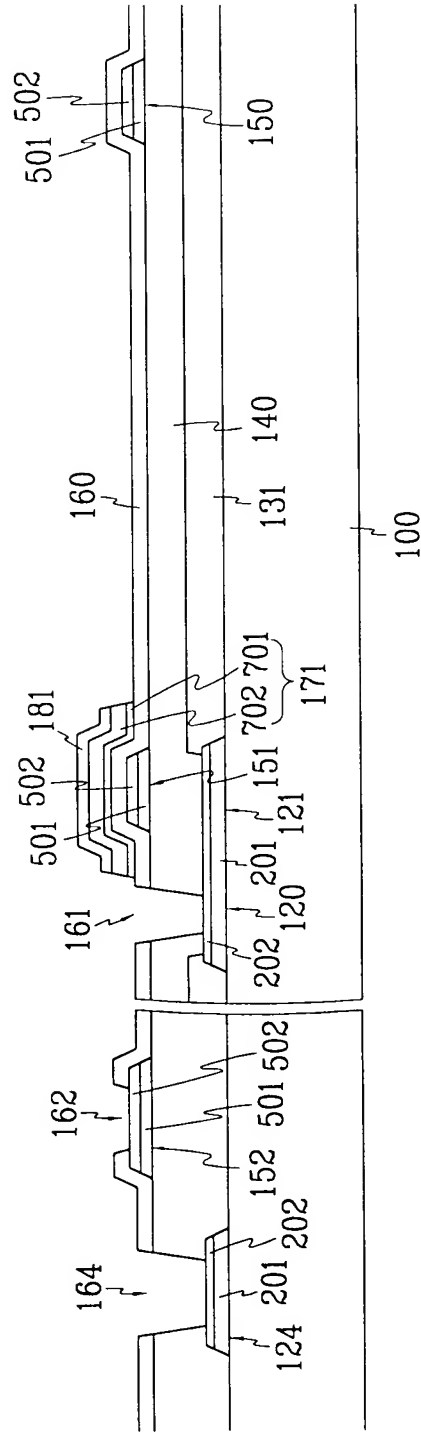


FIG. 25

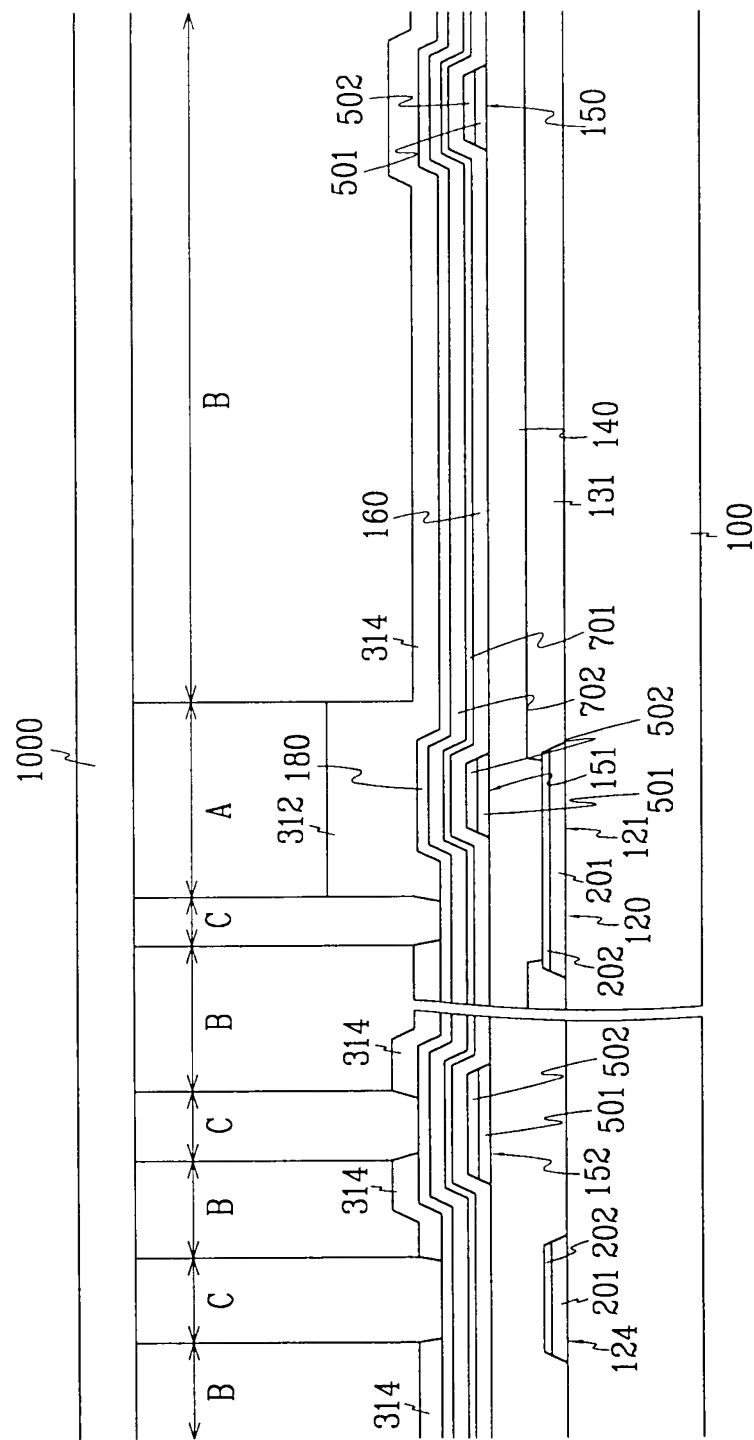


FIG. 26

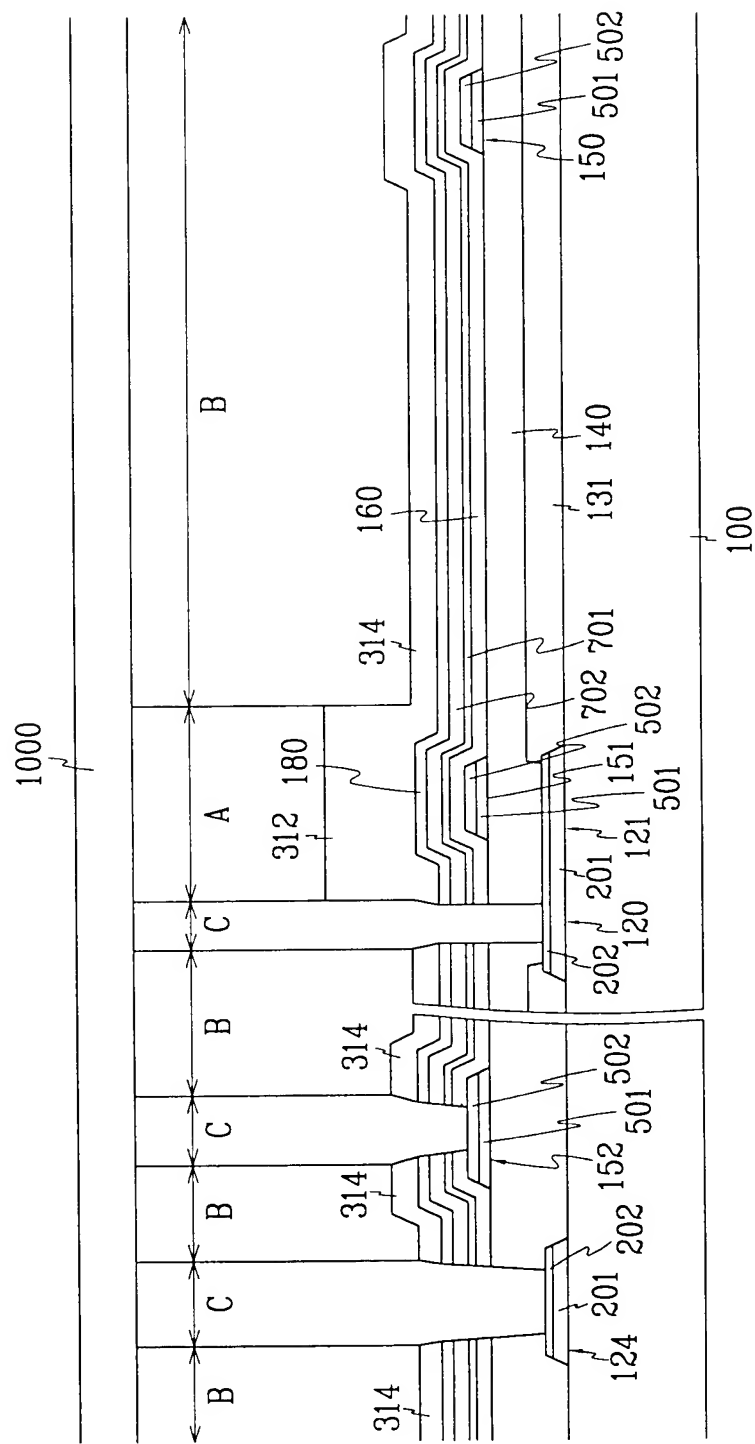
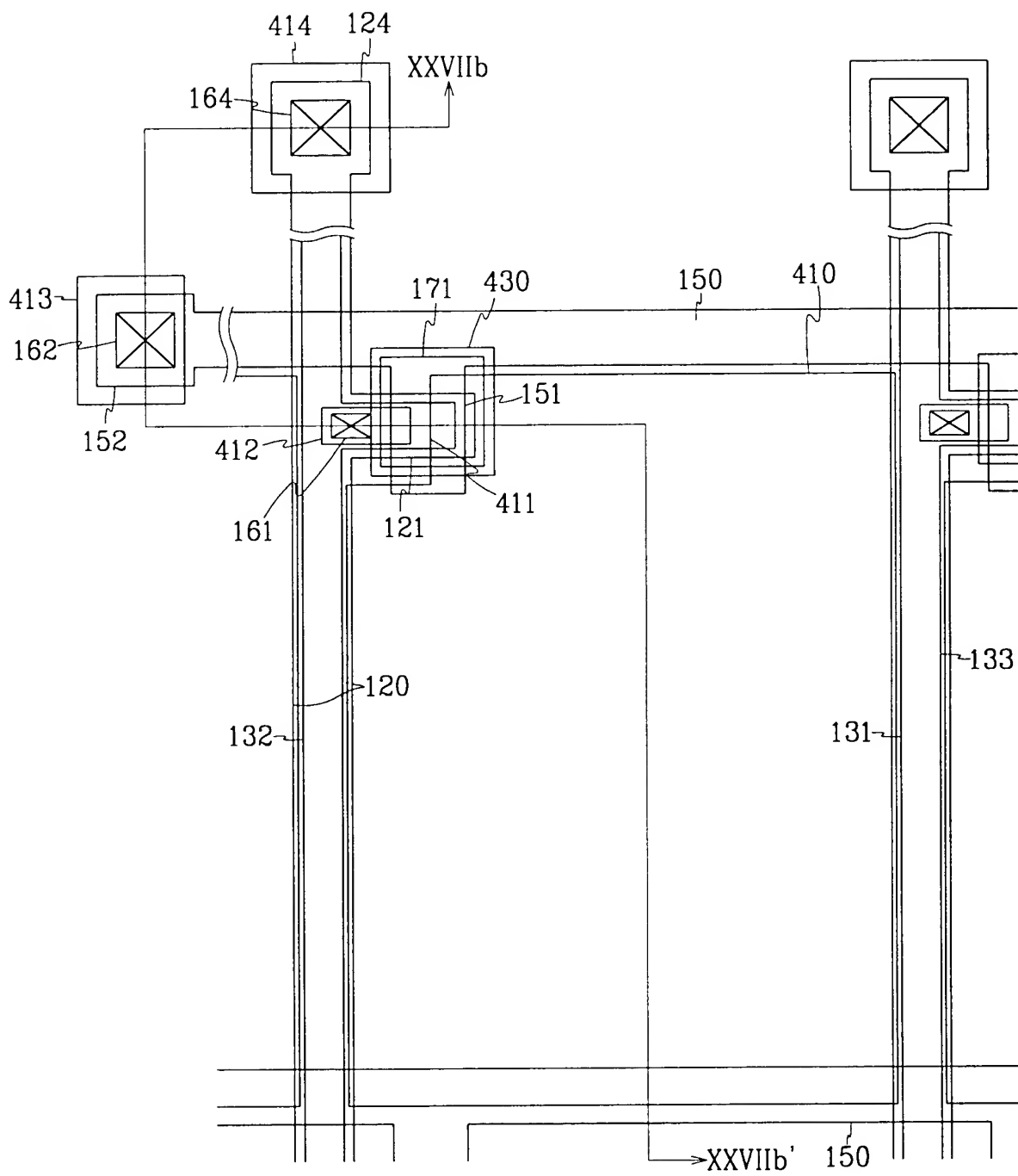


FIG. 27A



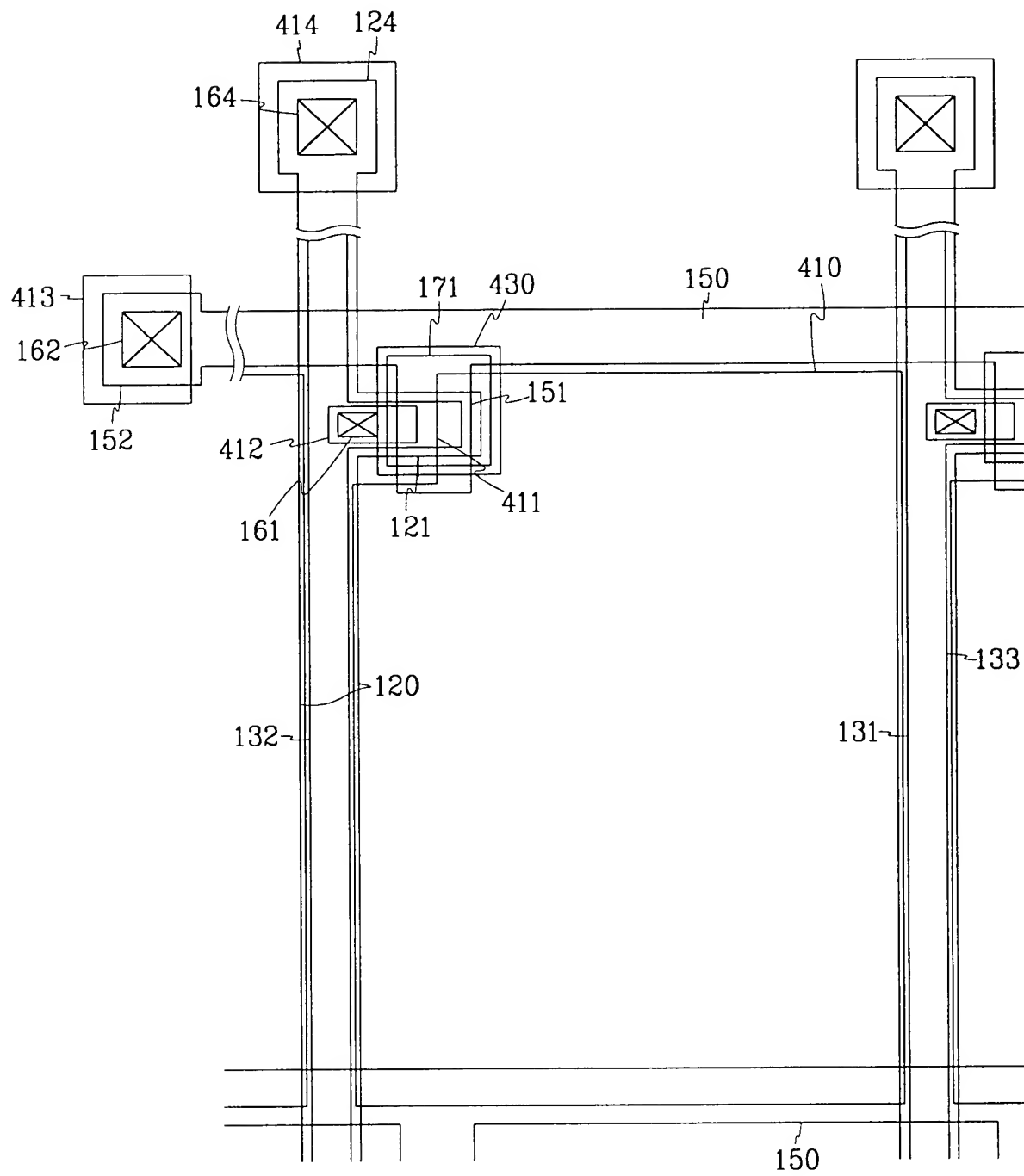


FIG. 29

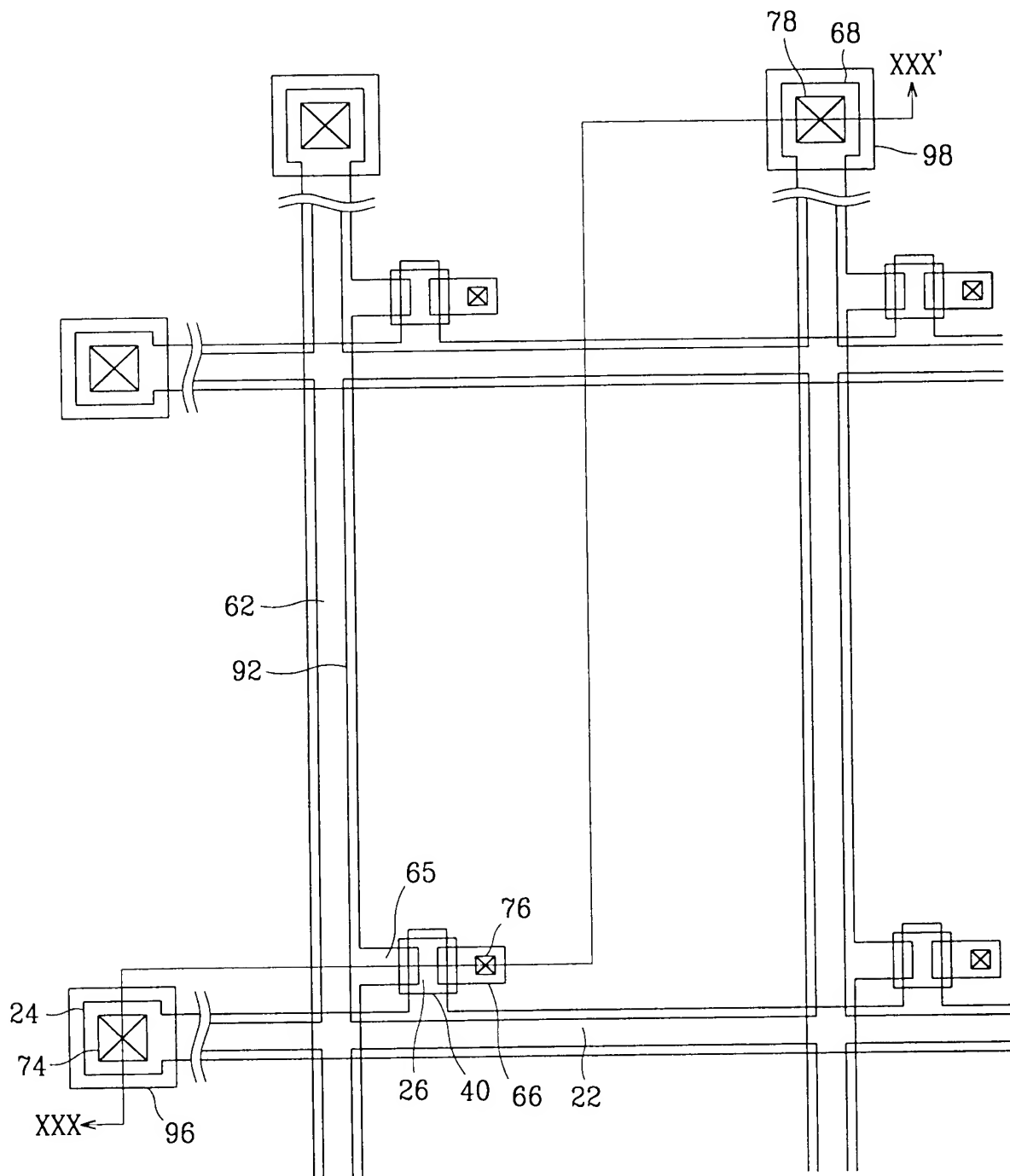


FIG.30

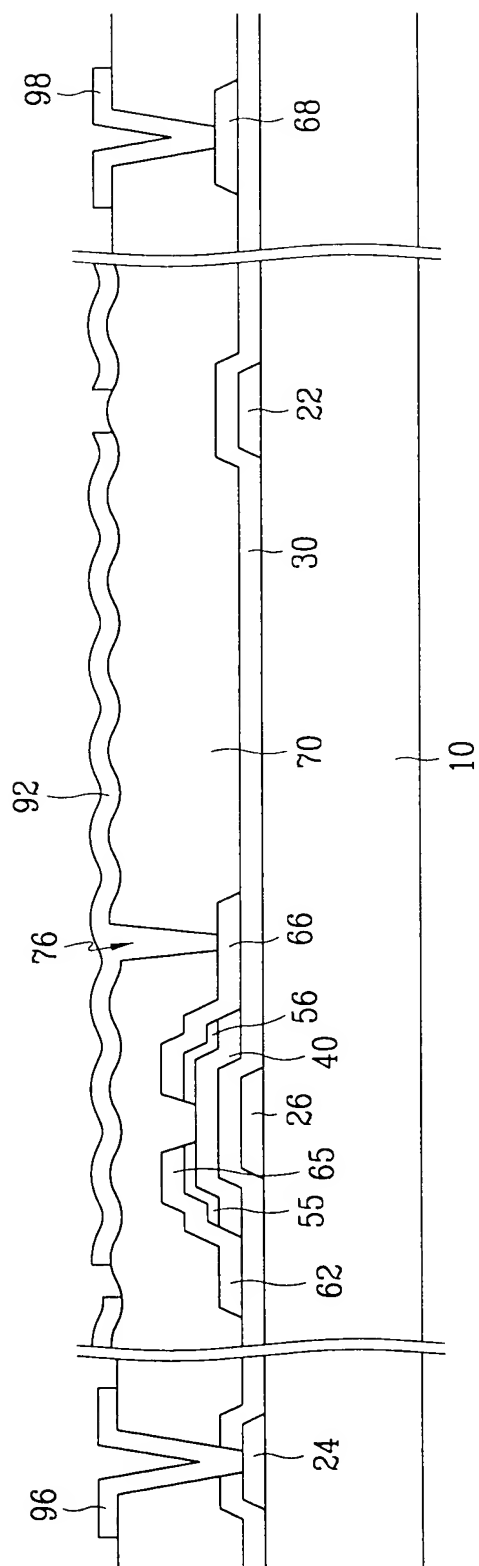


FIG.31A

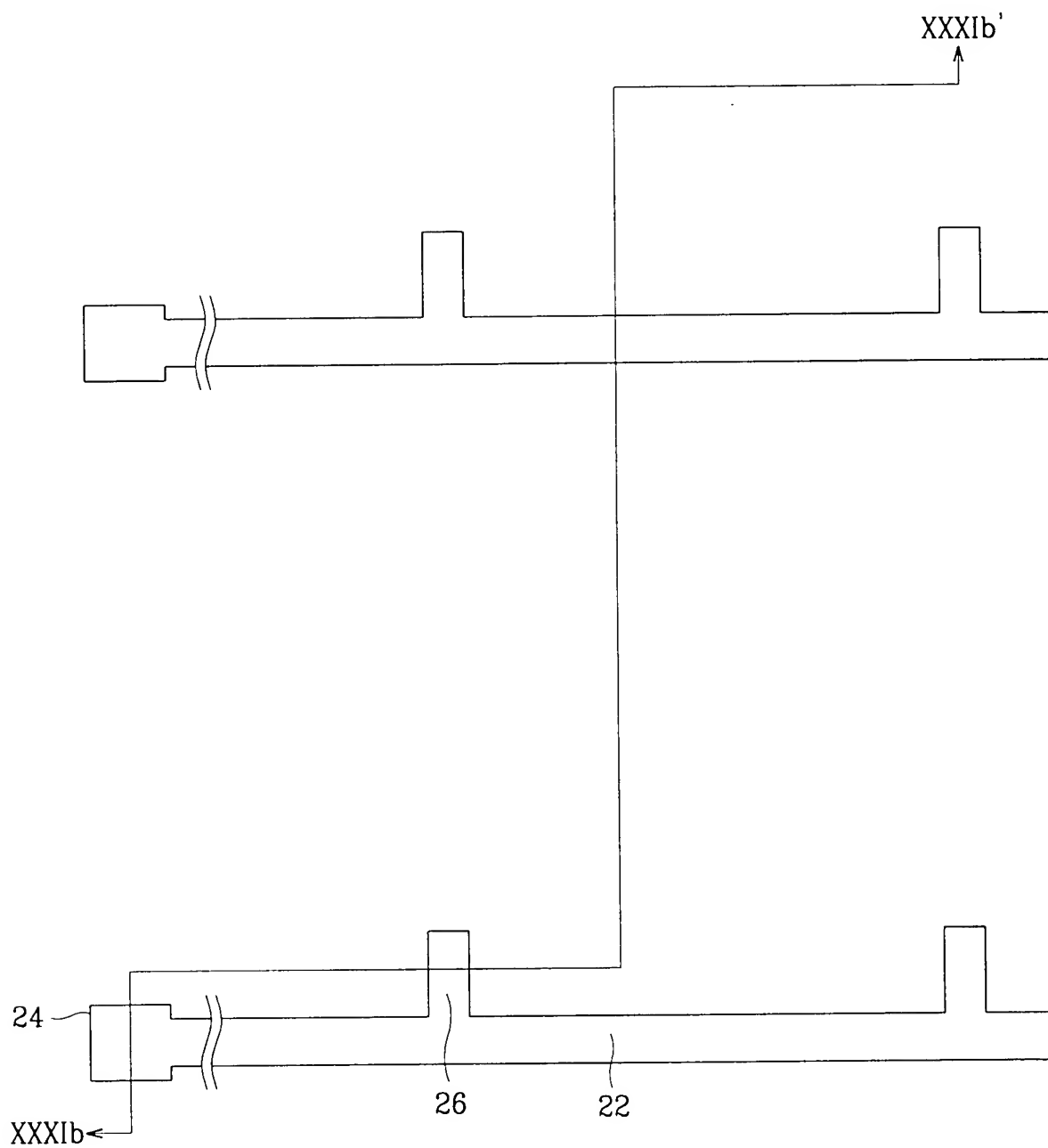


FIG. 31B

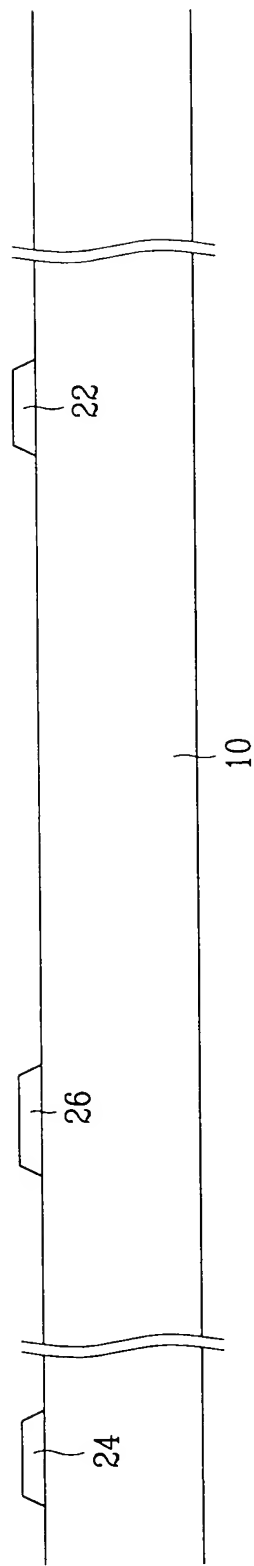


FIG.32A

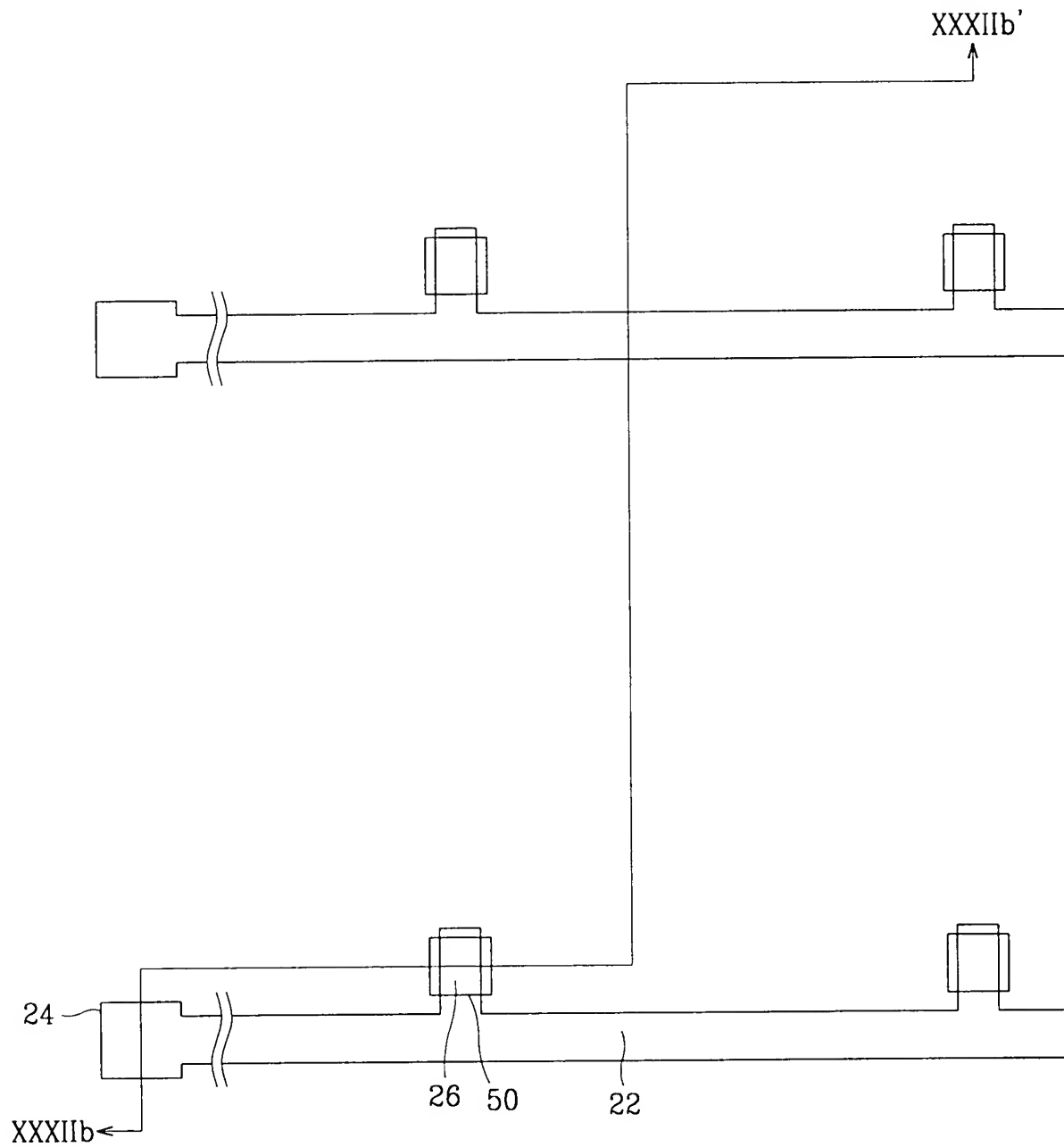


FIG. 32B

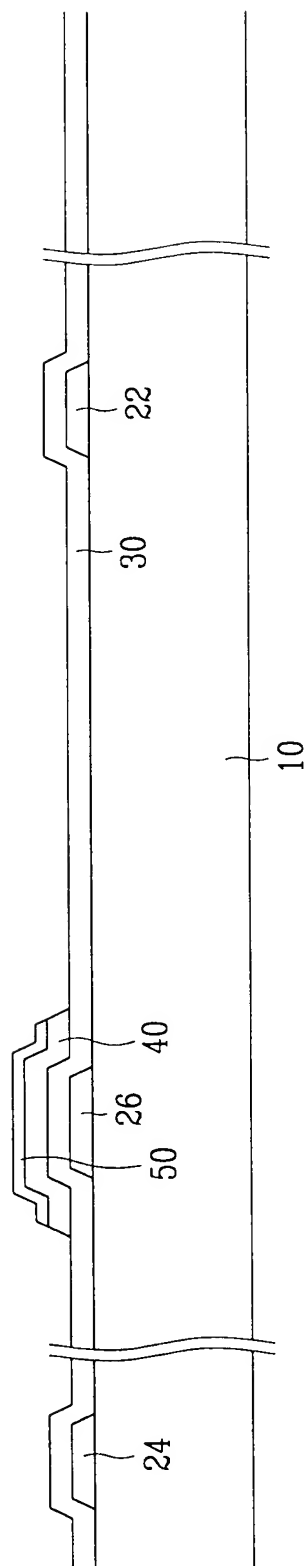


FIG.33A

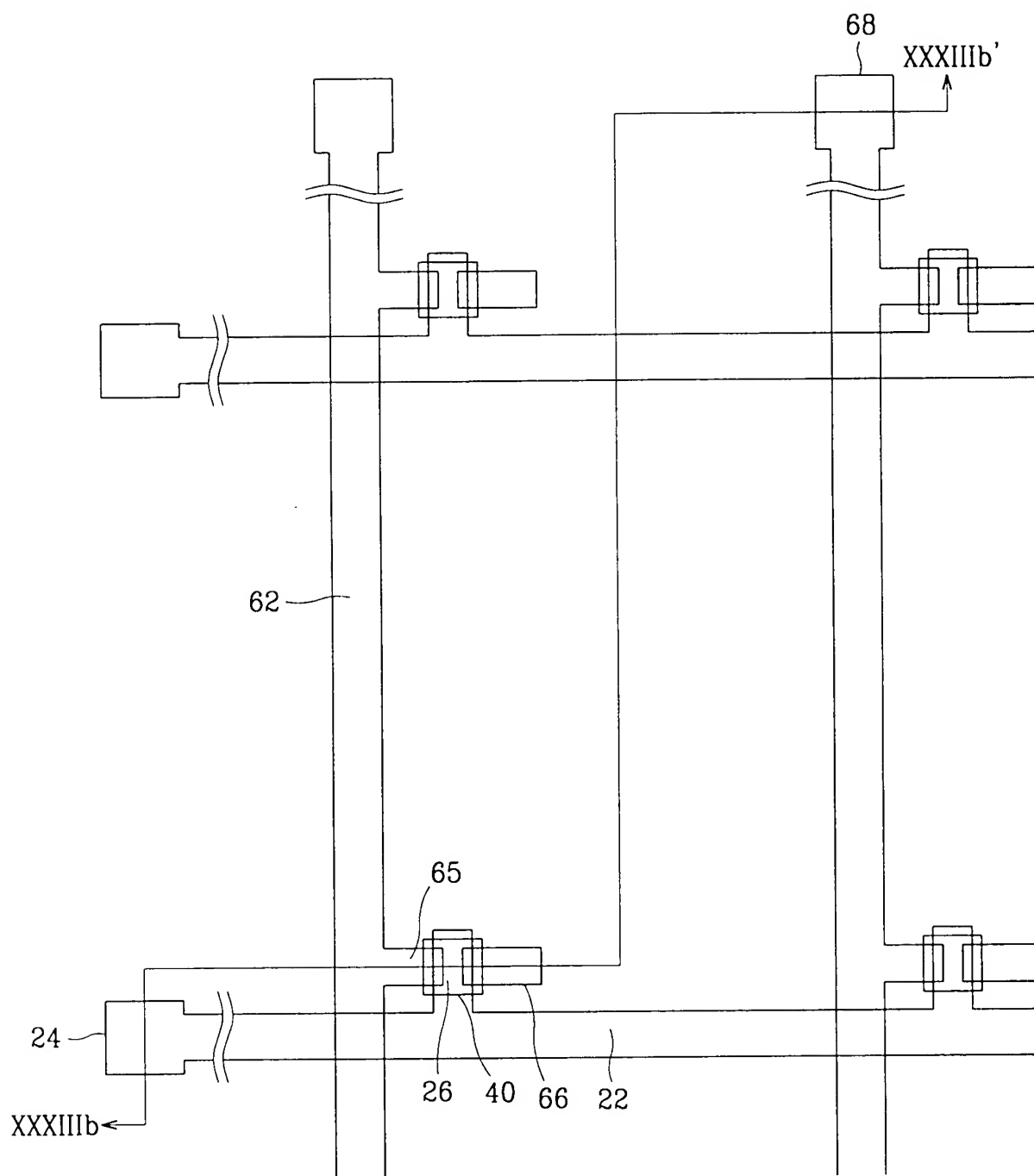


FIG. 33B

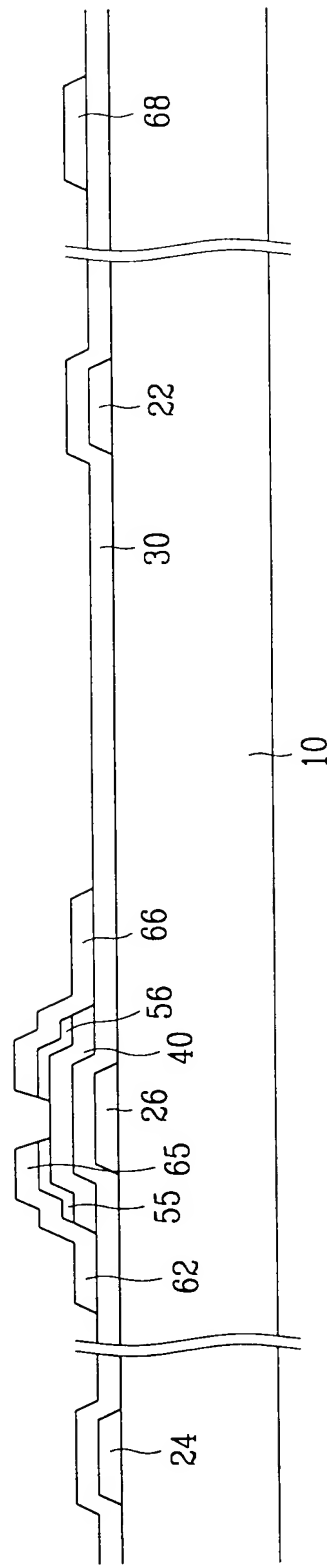


FIG. 34A

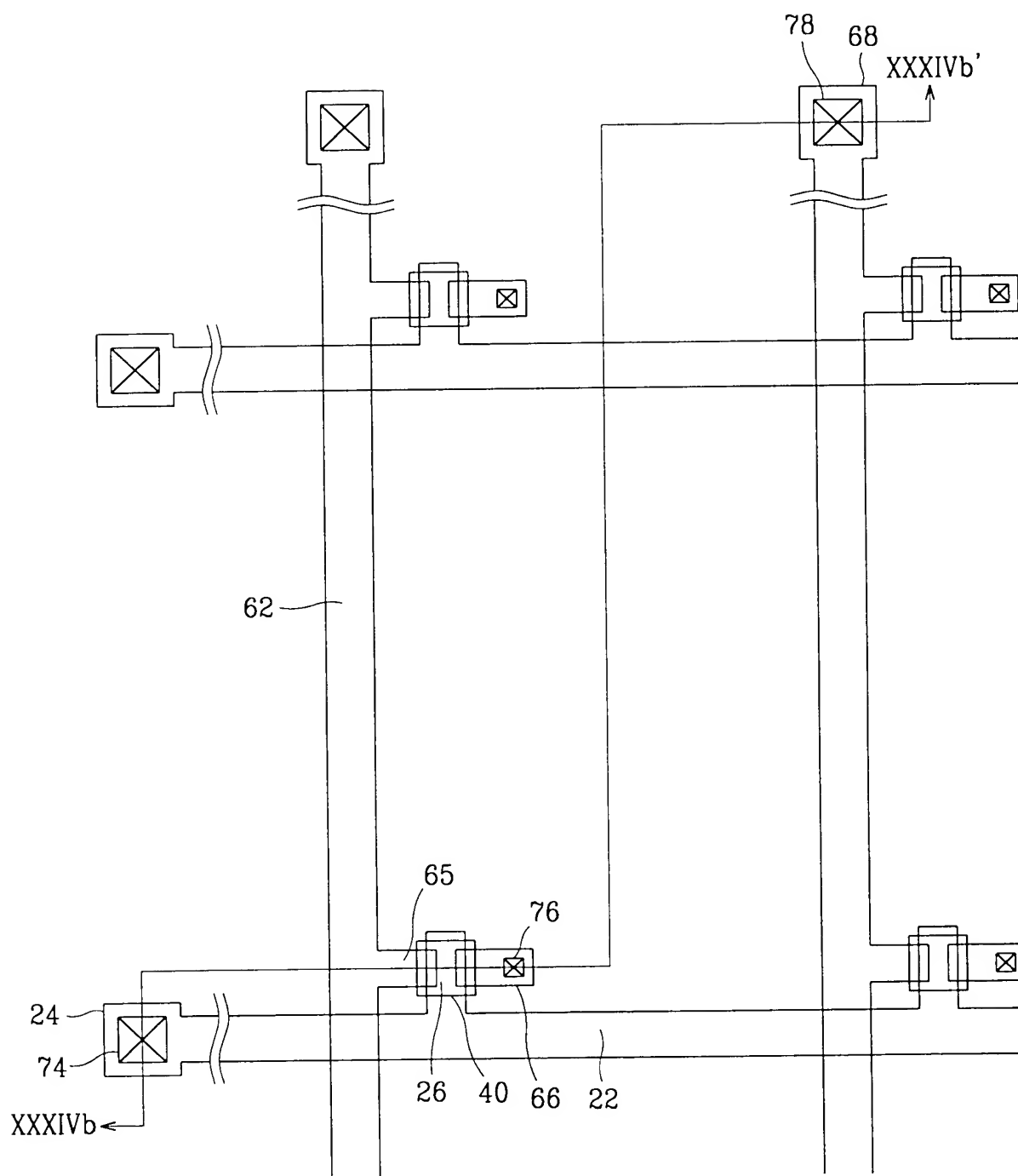


FIG. 34B

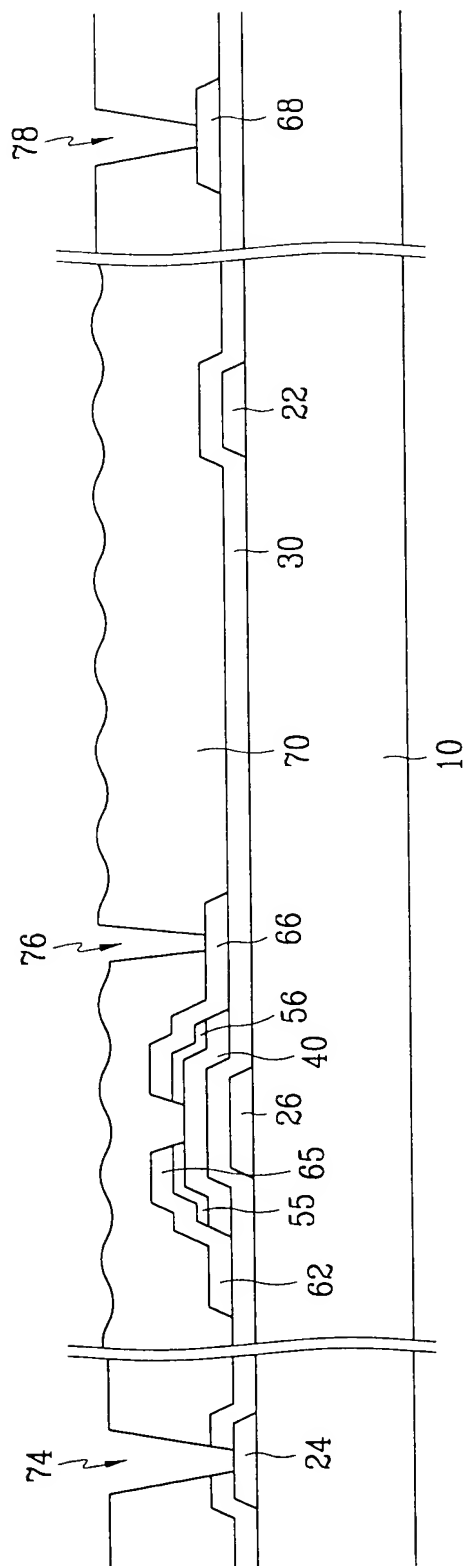


FIG. 35

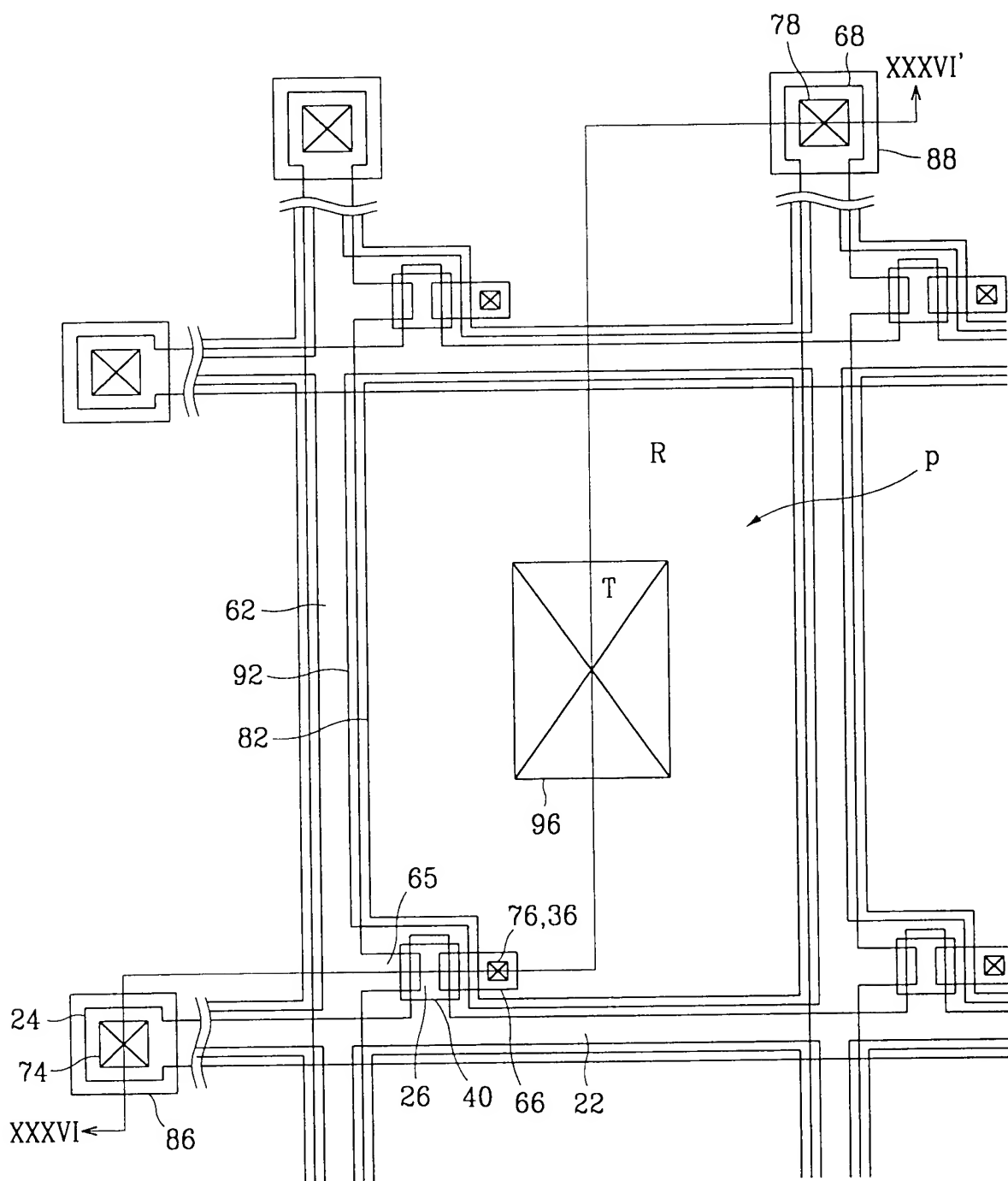
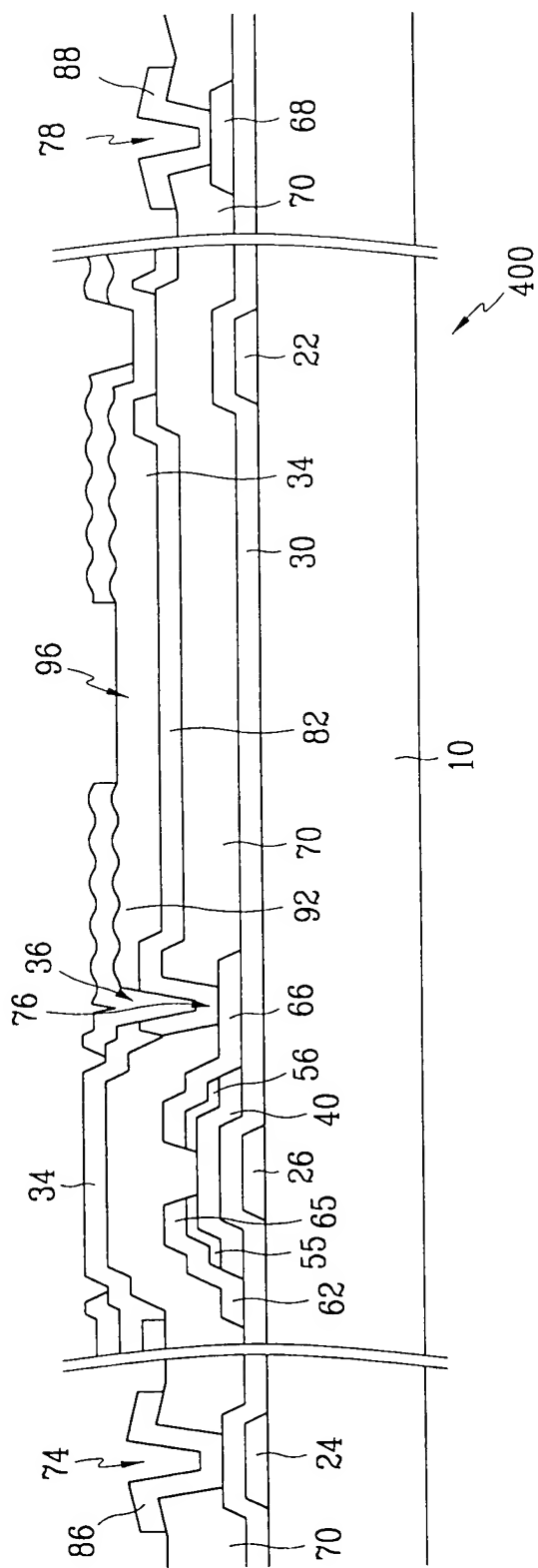


FIG. 36



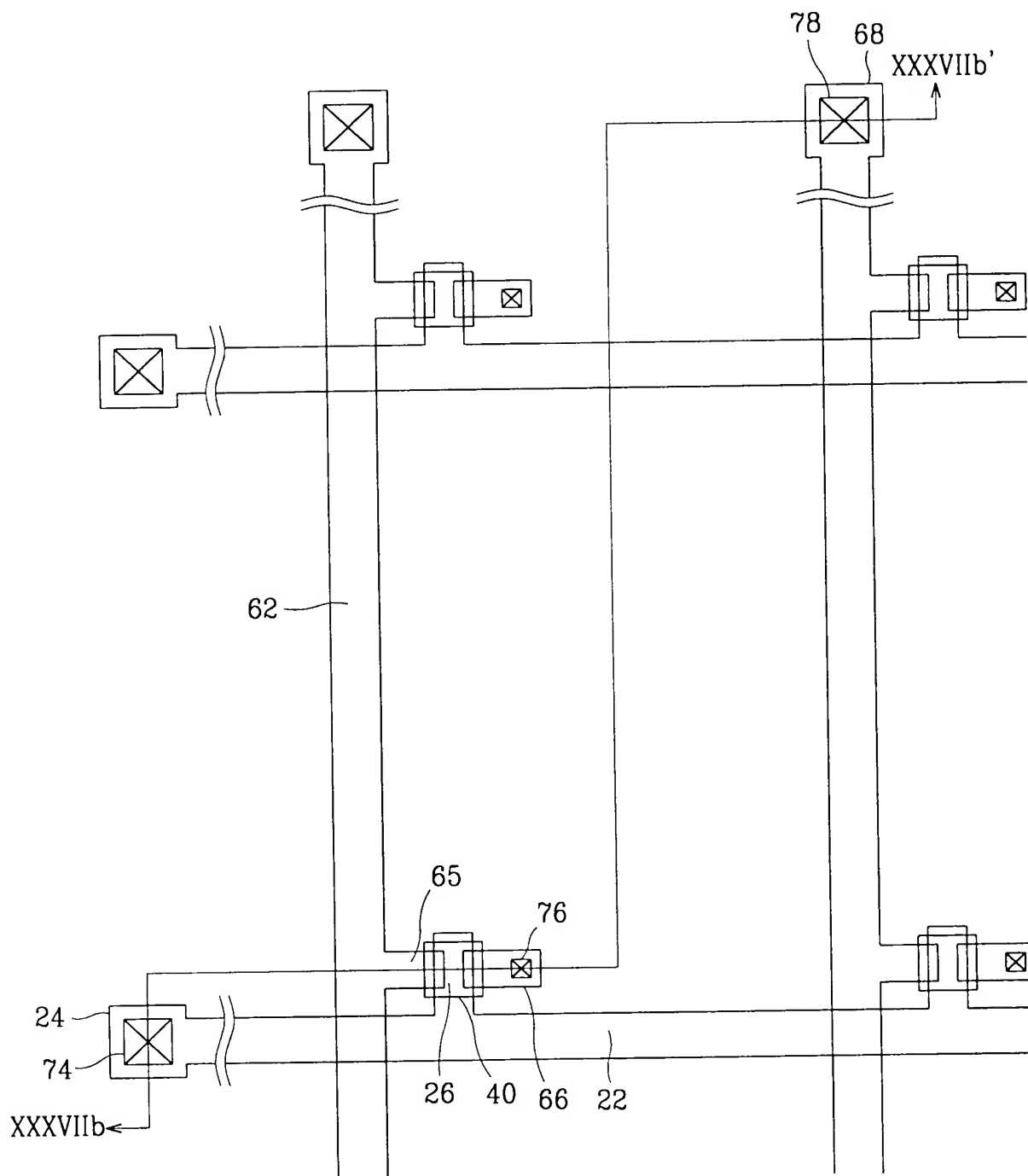


FIG. 37B

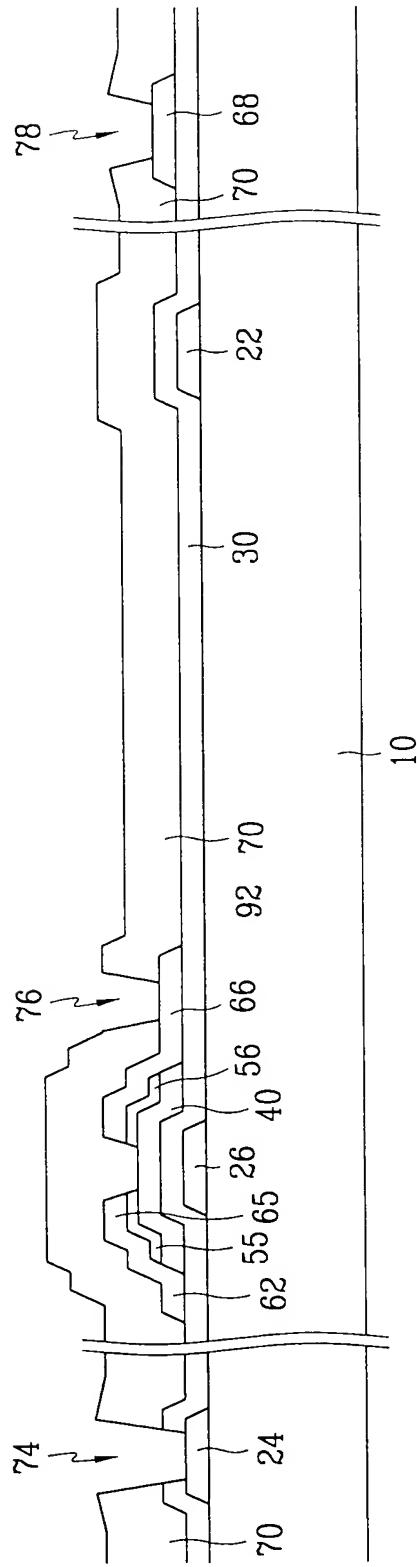


FIG.38A

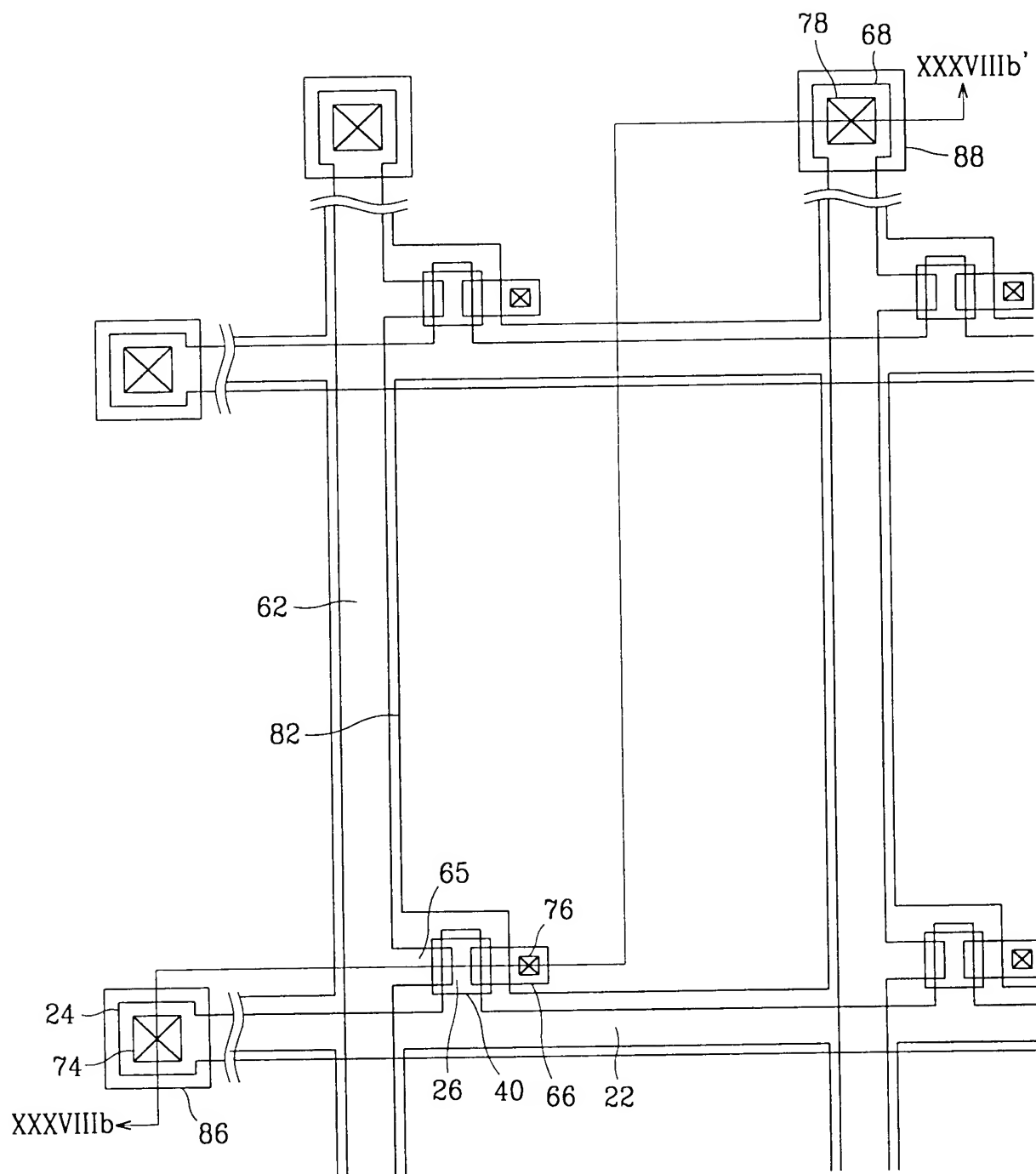


FIG. 38B

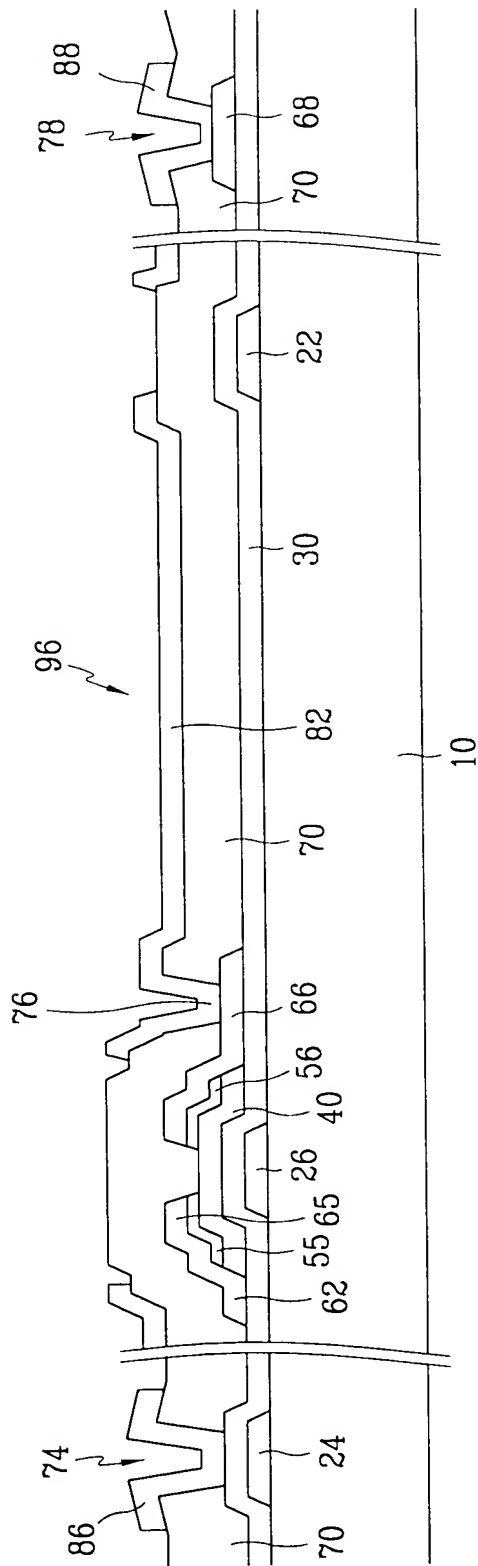


FIG. 39A

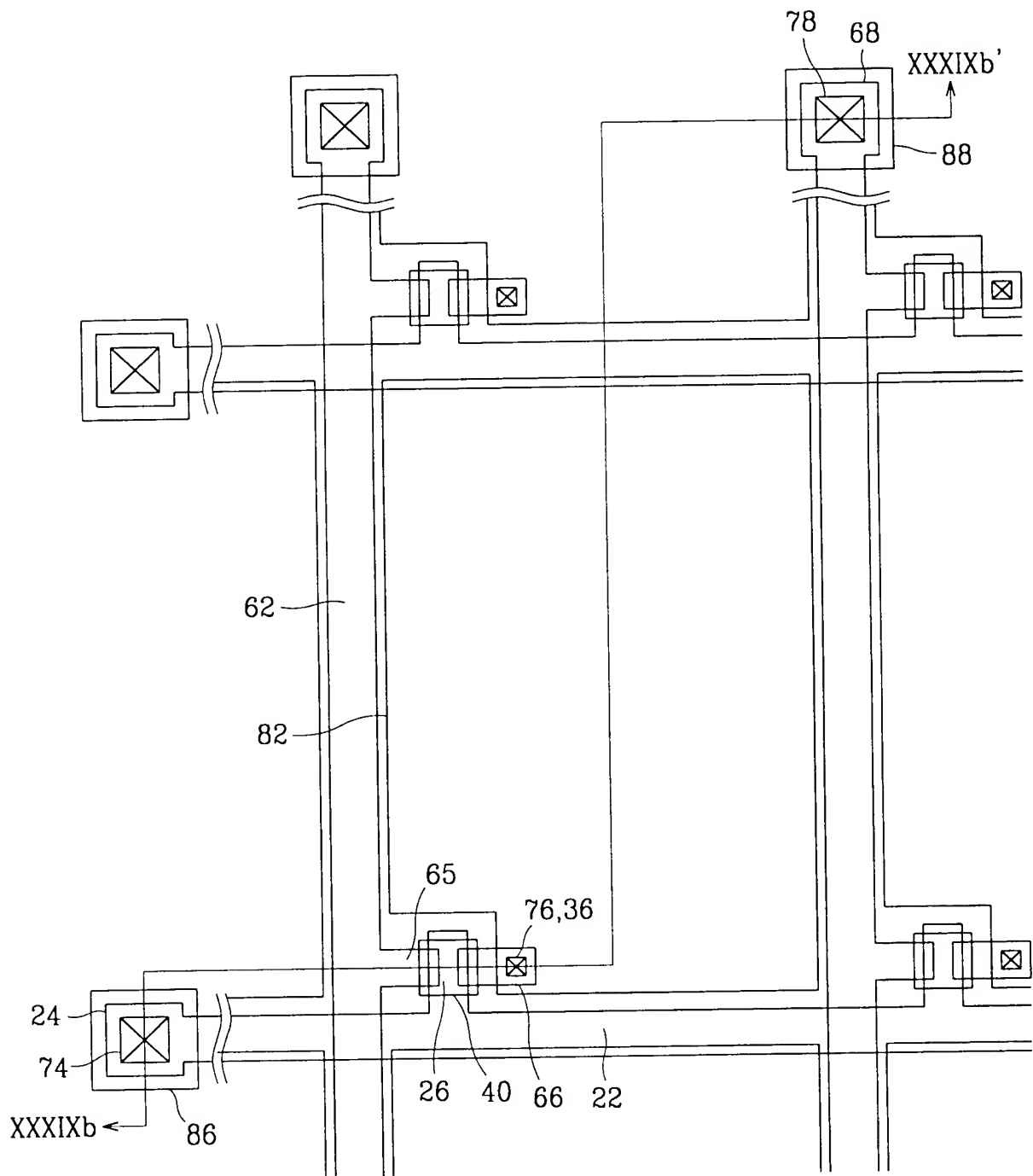


FIG. 39B

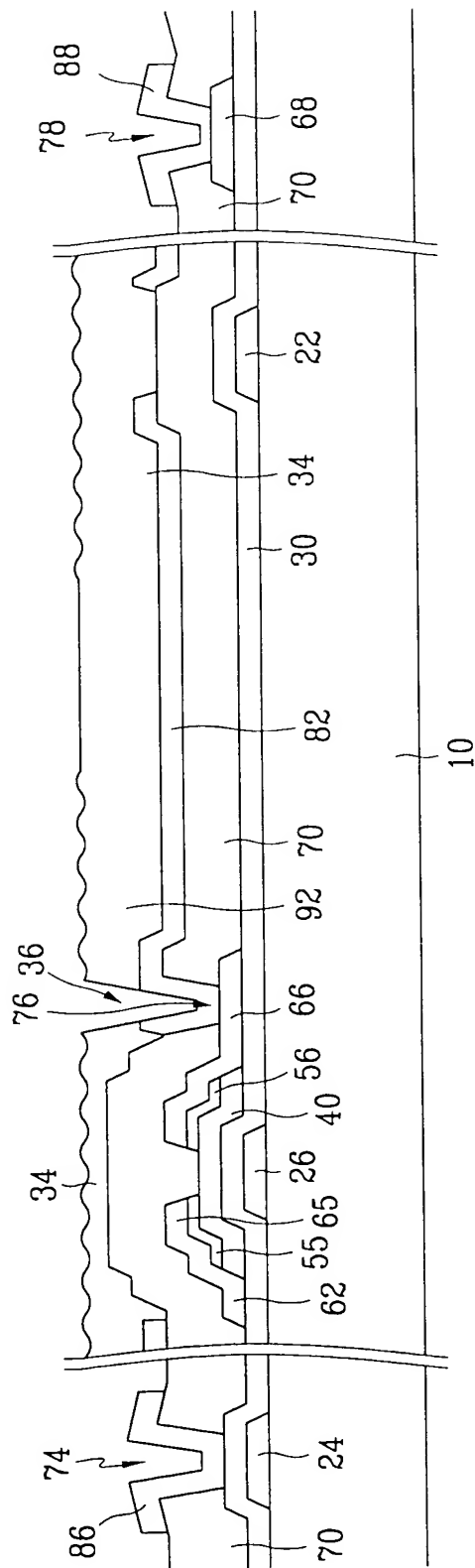


FIG. 40

